

A 0.073-mm² 10-GS/s 6-bit Time-Domain Folding ADC in 65-nm CMOS with Inherent DEM

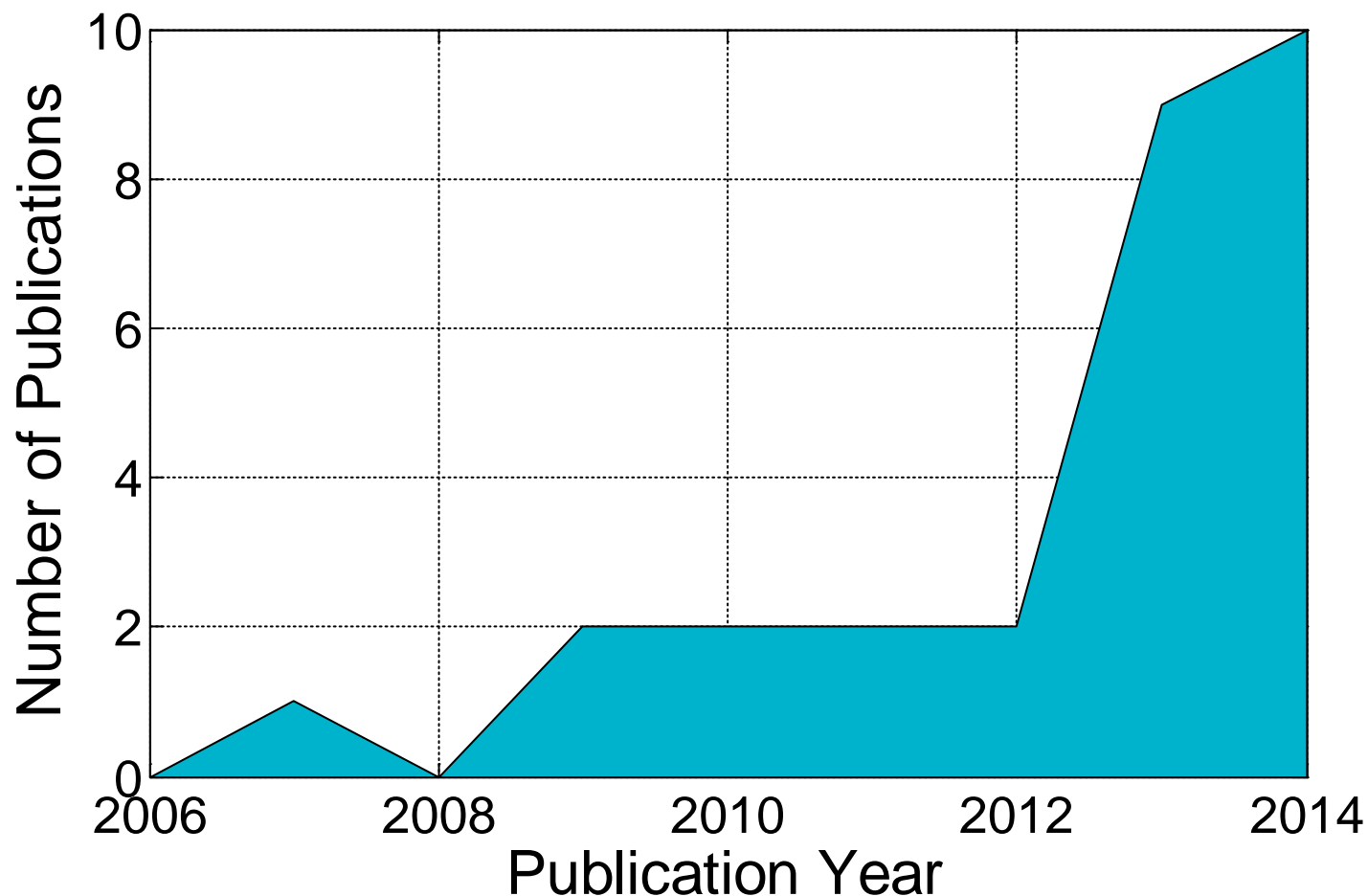
Shuang Zhu, Benwei Xu, Bo Wu, Kiran Soppimath, and Yun Chiu

Analog and Mixed-Signal Lab, Texas Analog Center of Excellence
University of Texas at Dallas

Outline

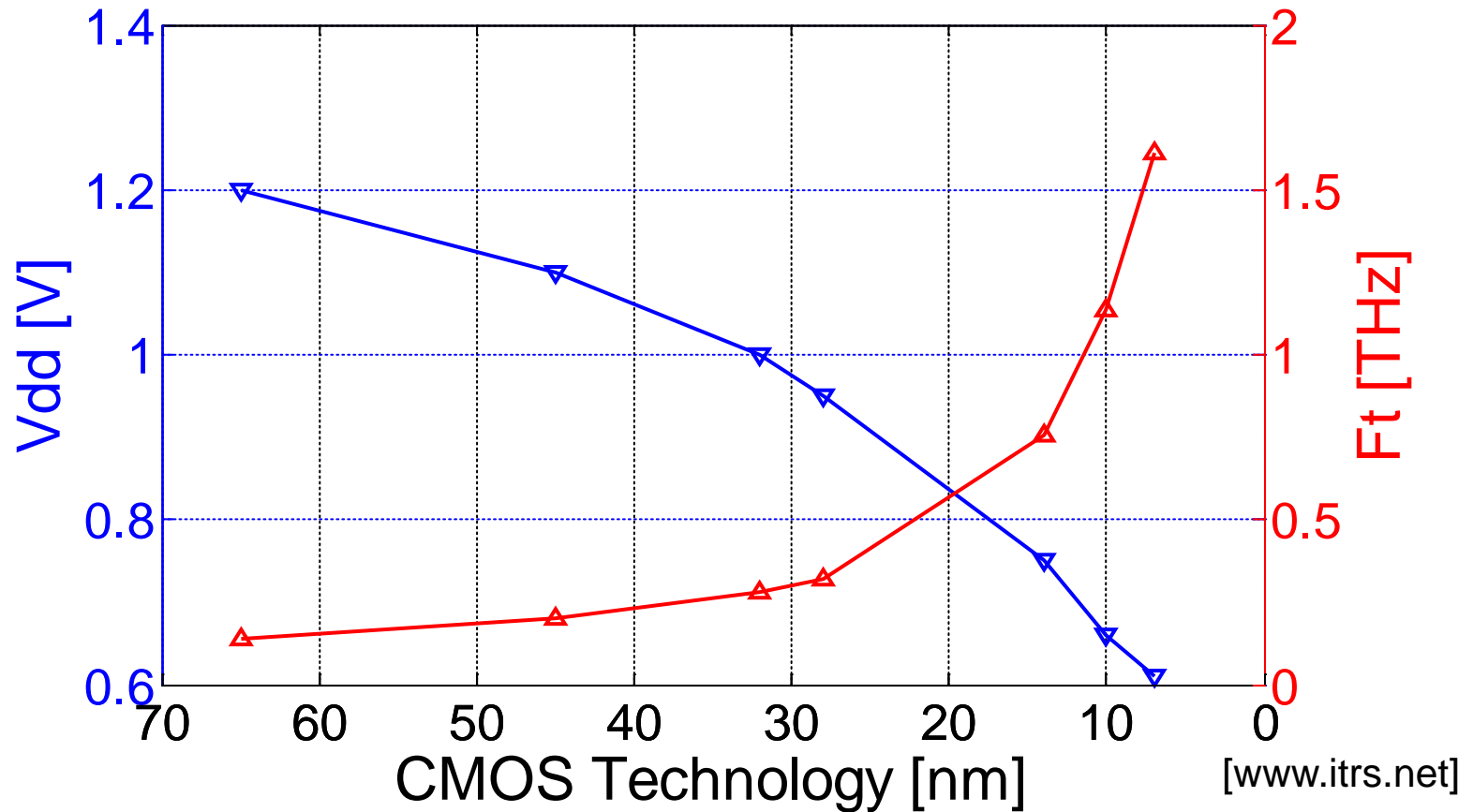
- **Motivation for Time Domain**
- Time to Digital Converter
- Voltage to Time Converter
- Other Circuits
- Measurement Results
- Conclusion

Publications of Time-Domain ADCs



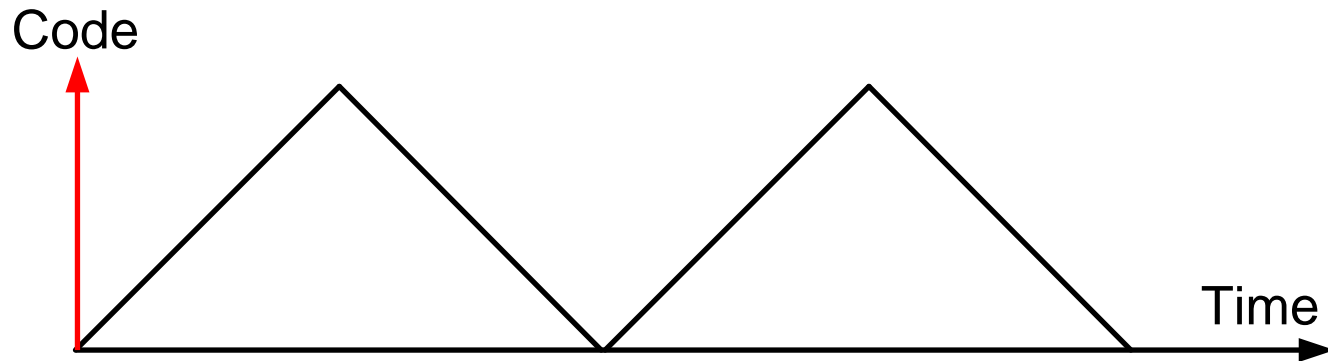
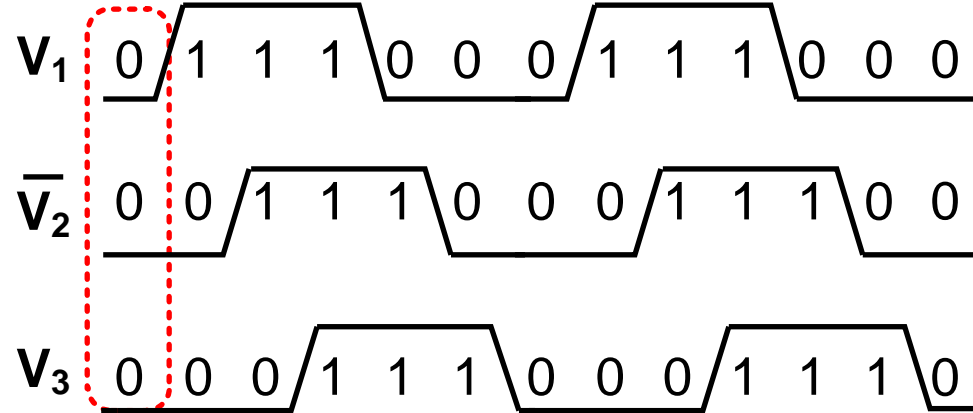
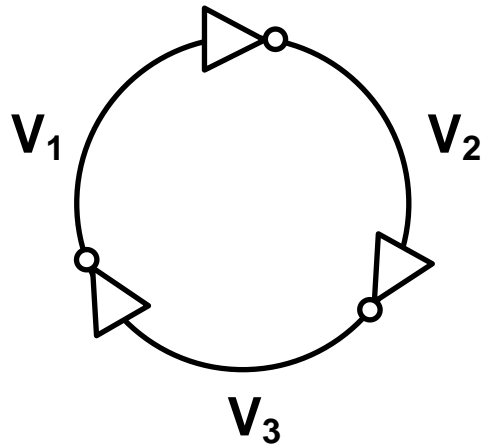
Source: ISSCC, VLSI, CICC, ESSCIRC, ASSCC

CMOS Technology Trend



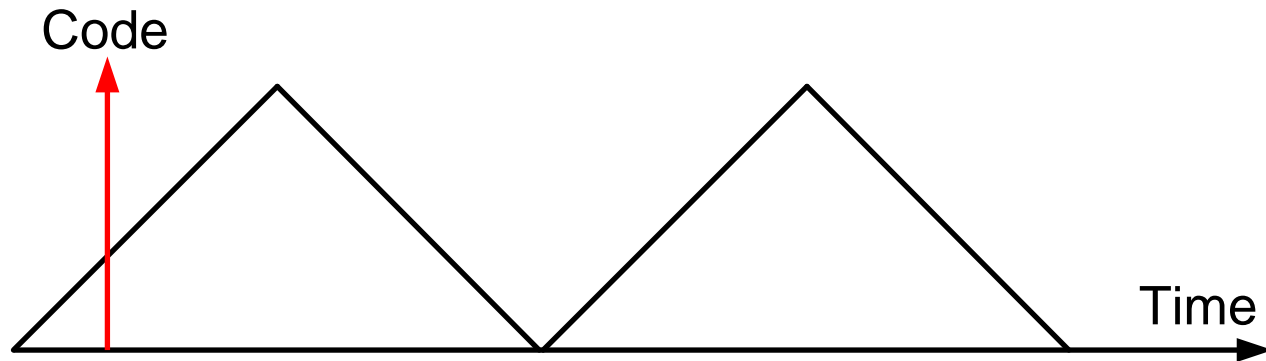
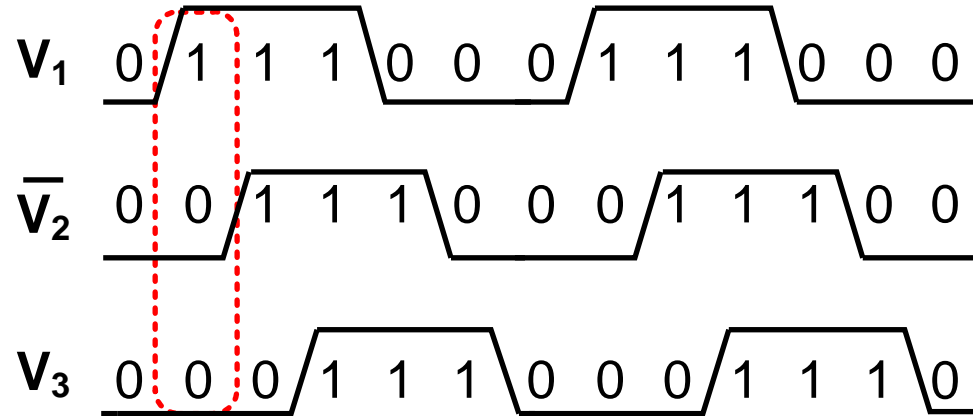
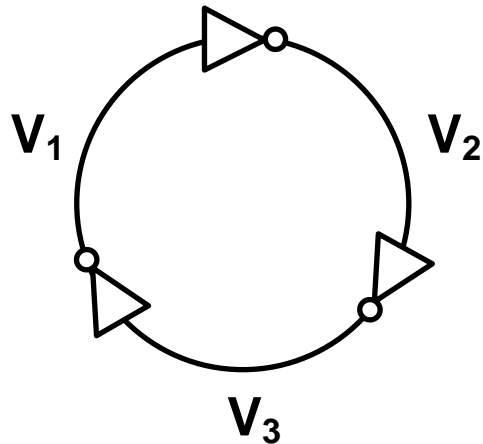
- Supply voltage $\downarrow \rightarrow$ voltage-domain losing resolution
- $F_t \uparrow \rightarrow$ time-domain gaining resolution

Ring Osc. (RO) Based Folding TDC



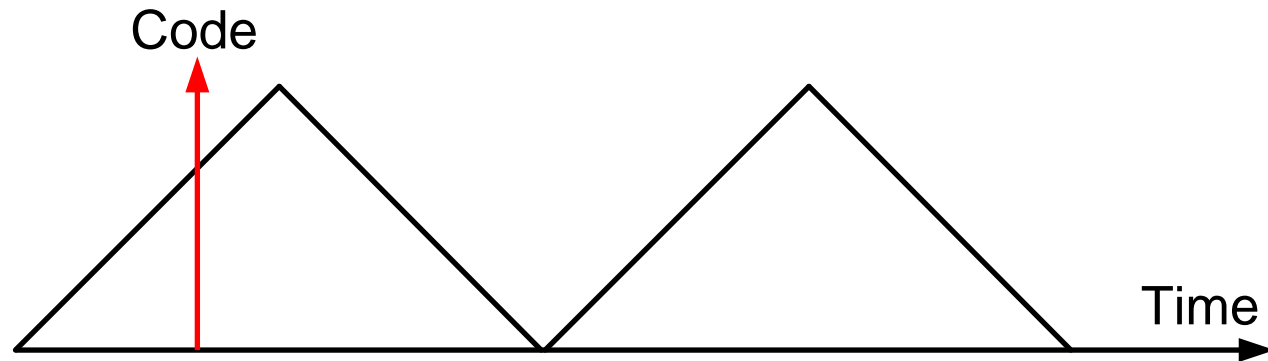
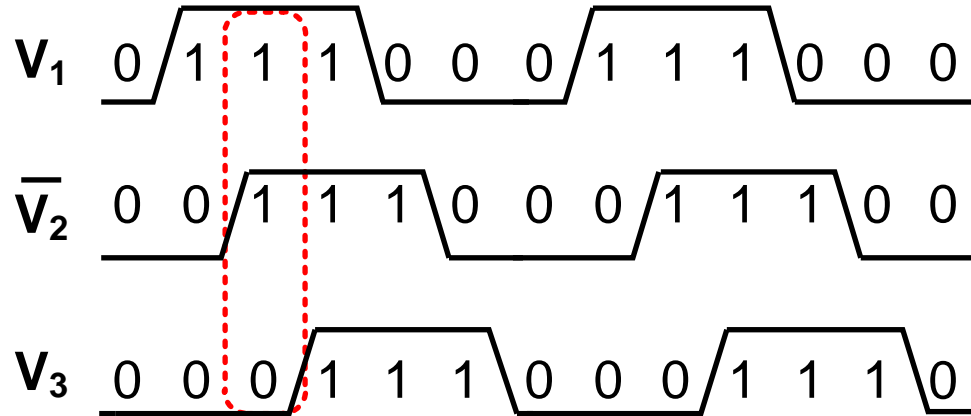
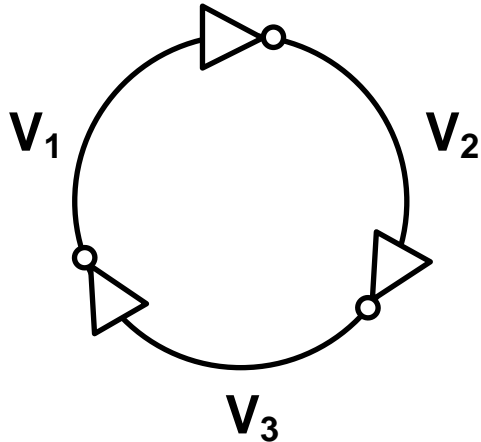
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- Quantization – LSB size of inv. delay

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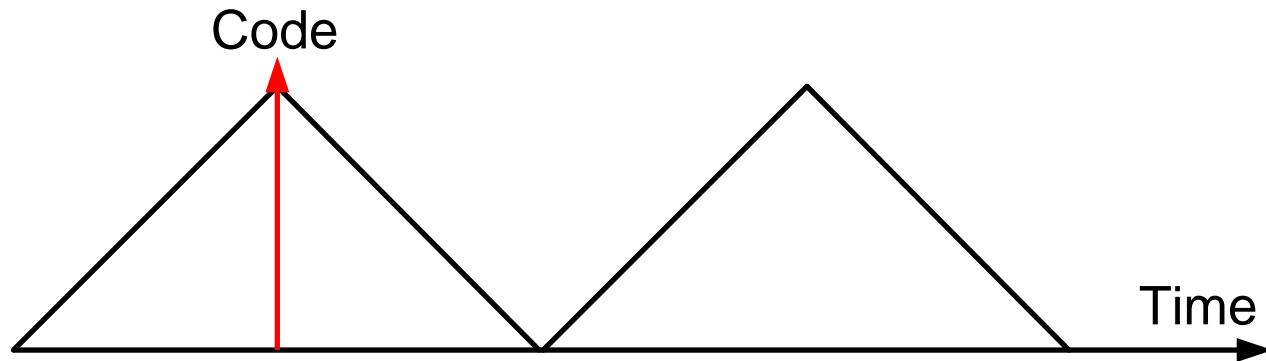
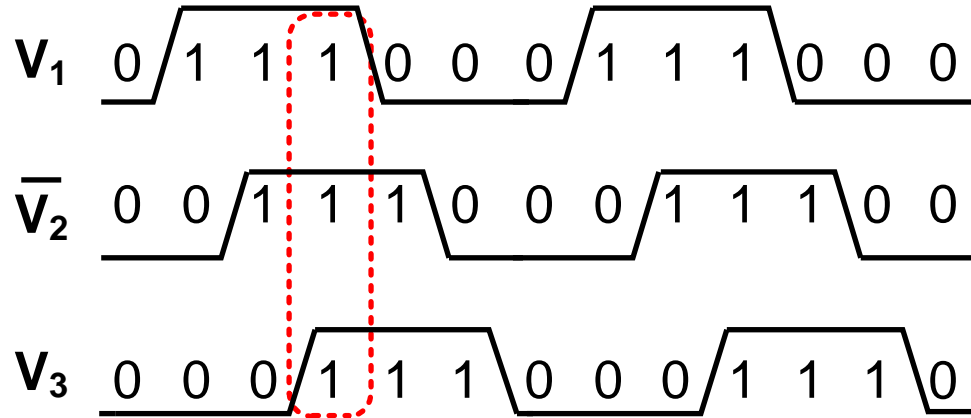
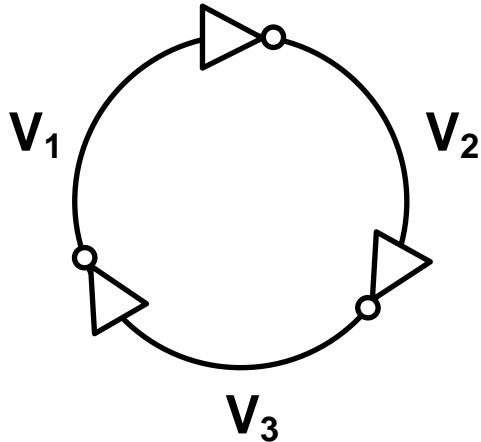
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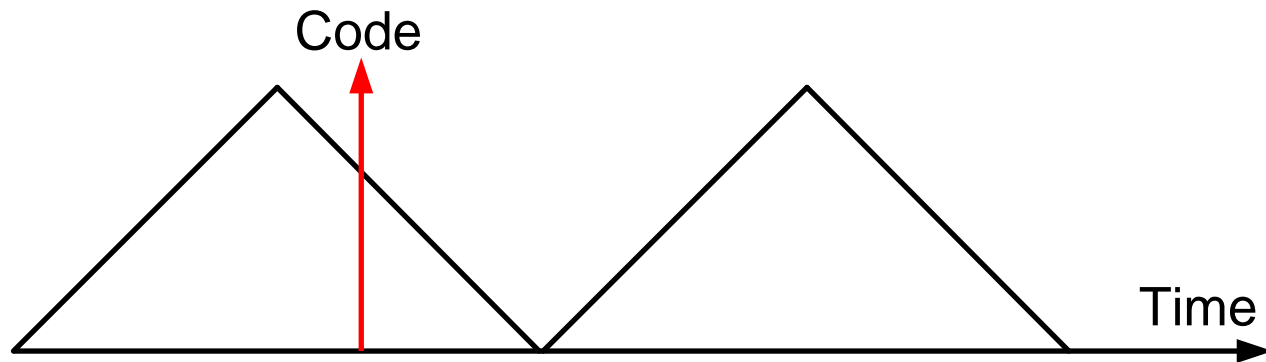
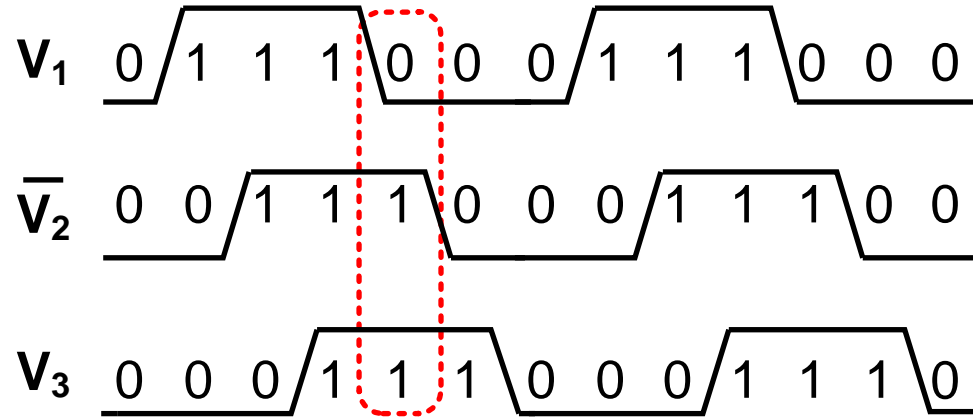
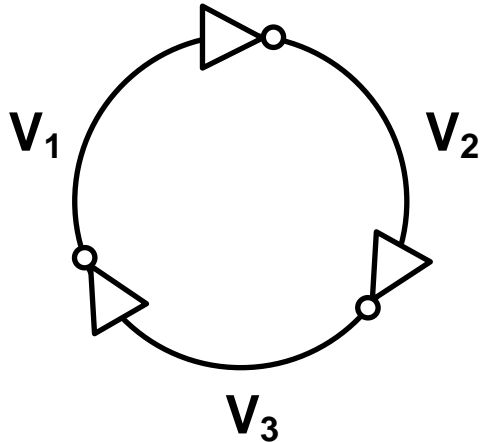
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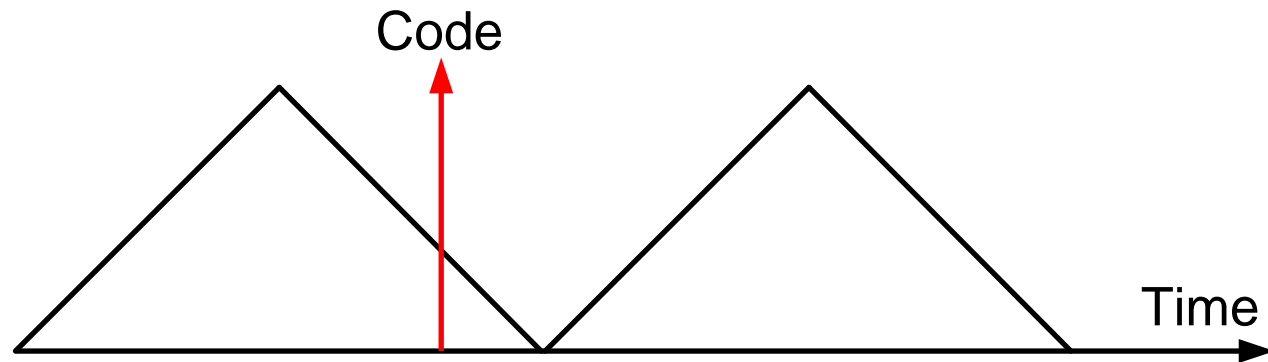
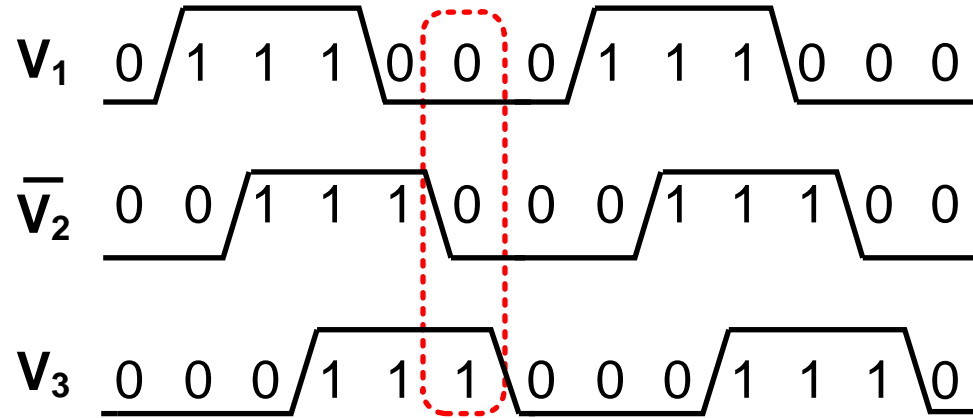
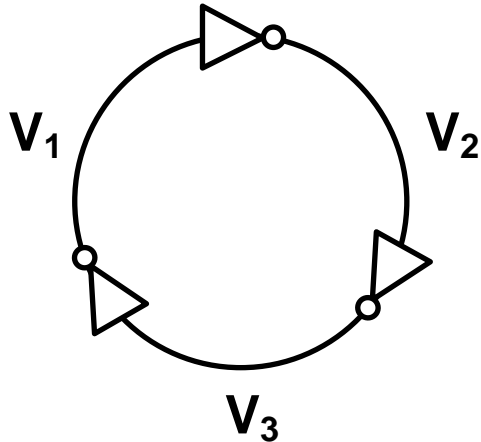
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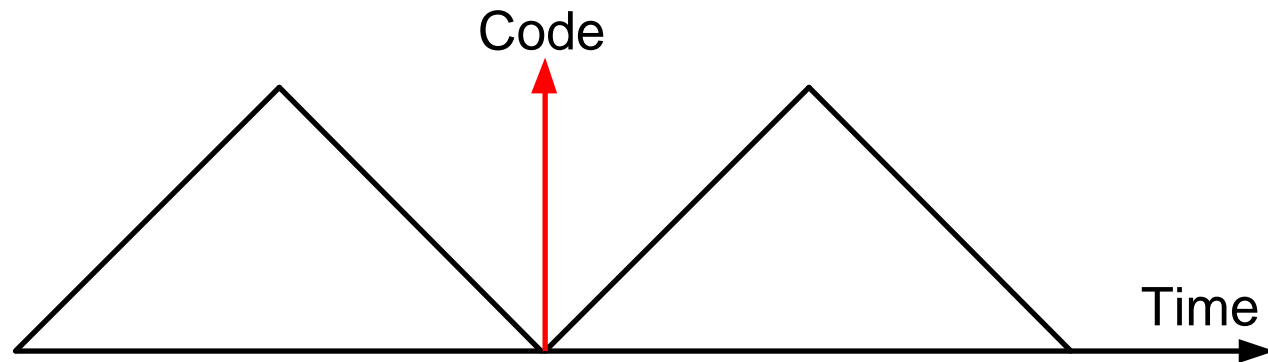
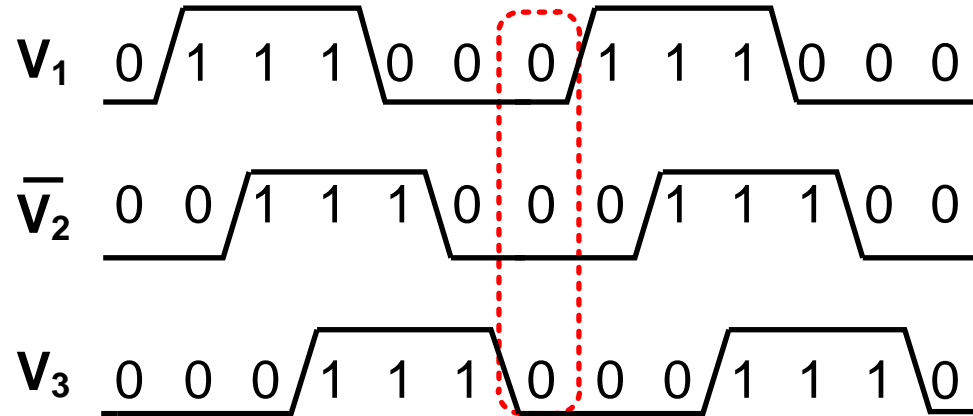
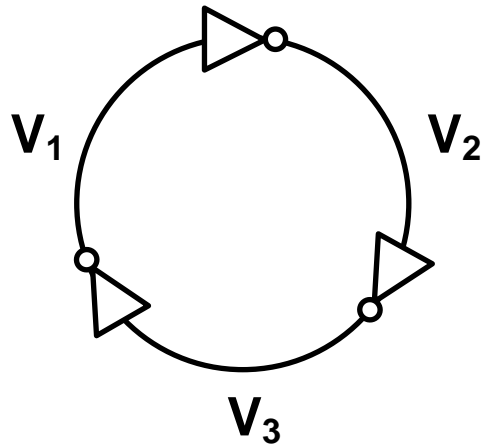
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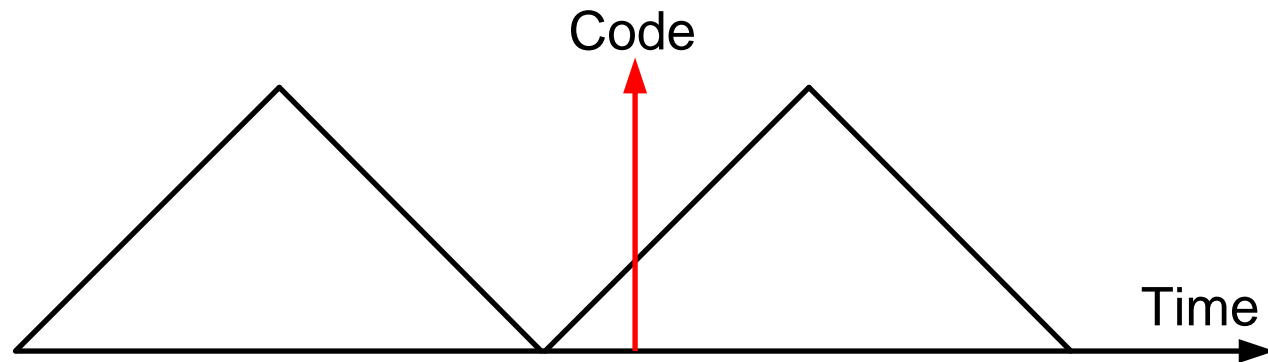
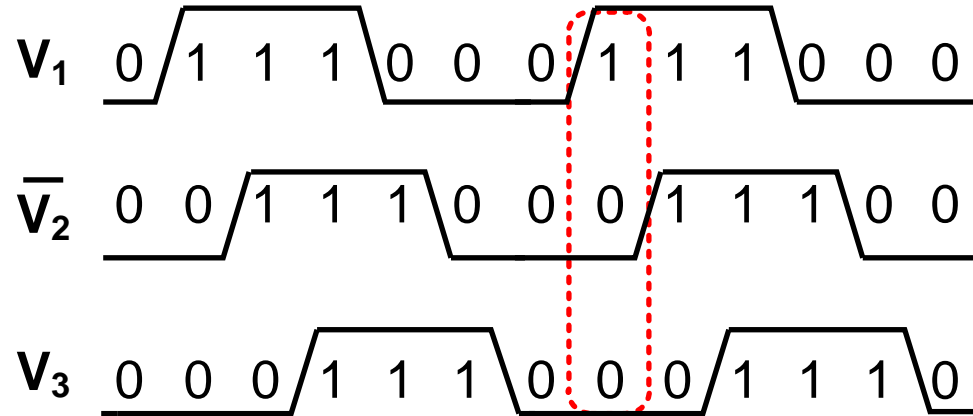
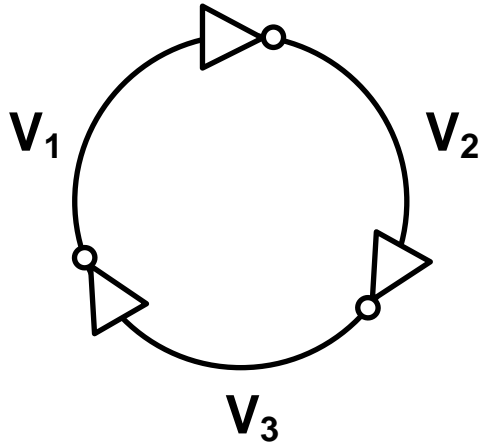
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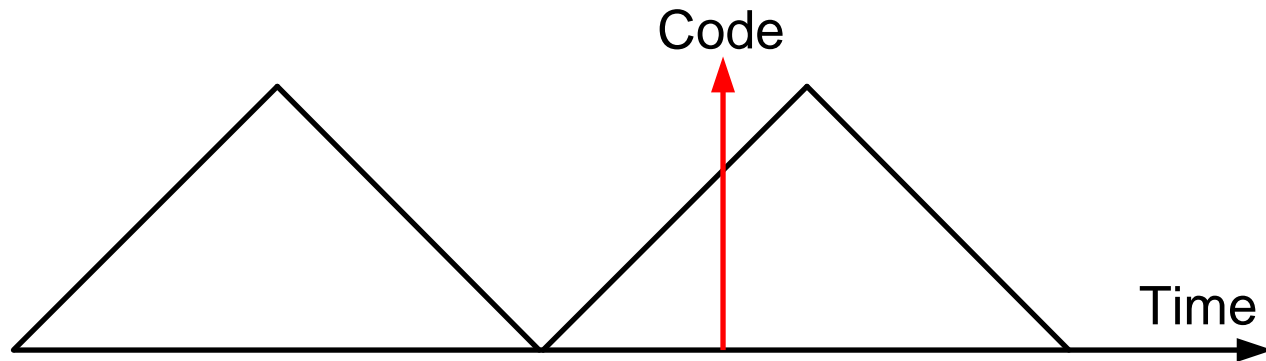
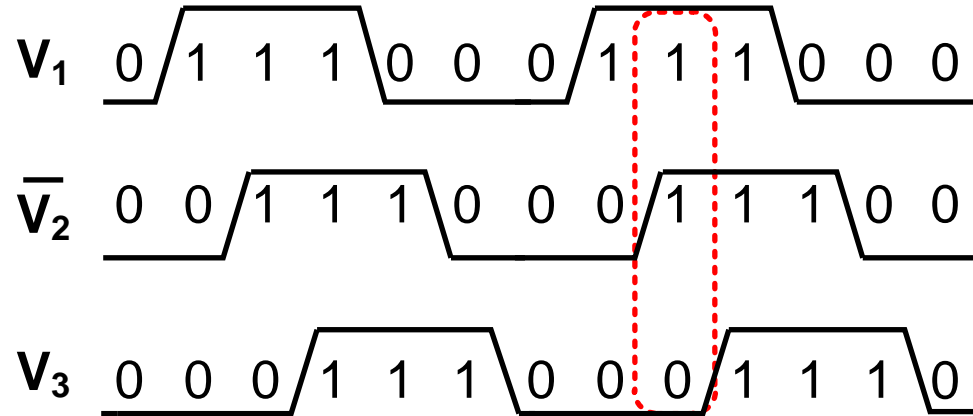
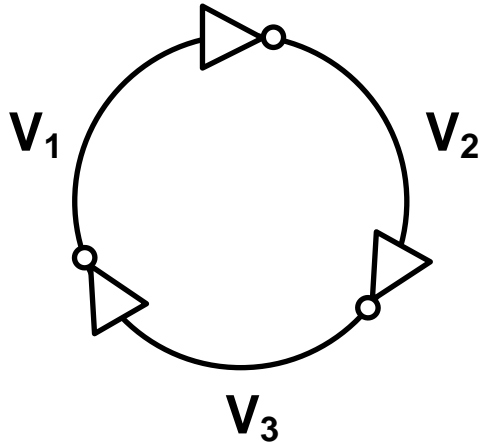
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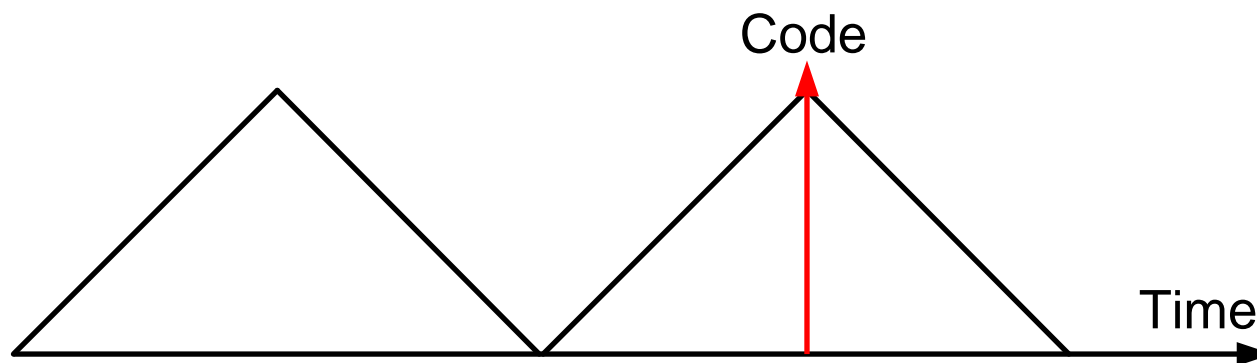
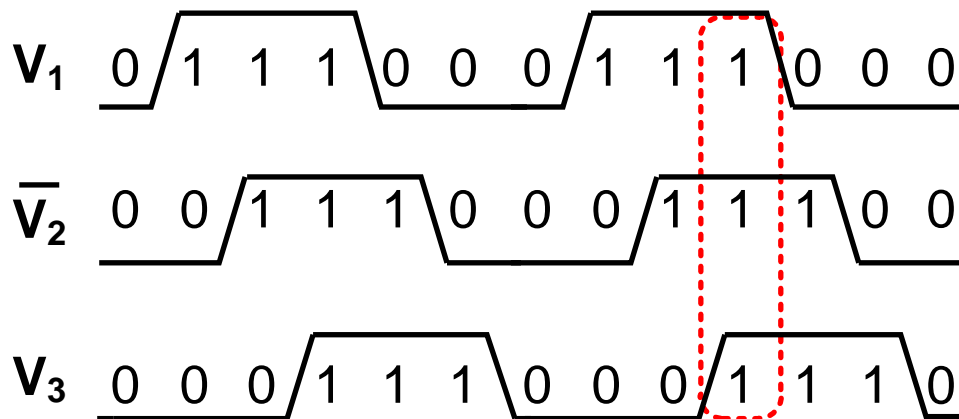
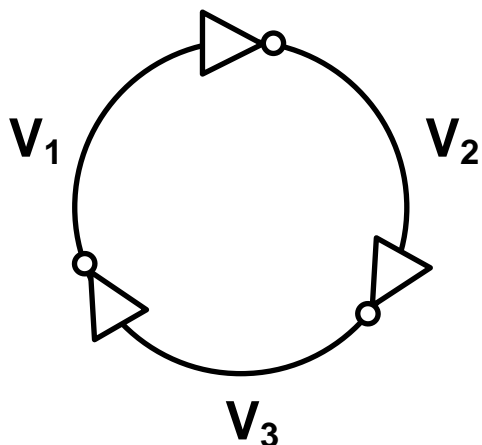
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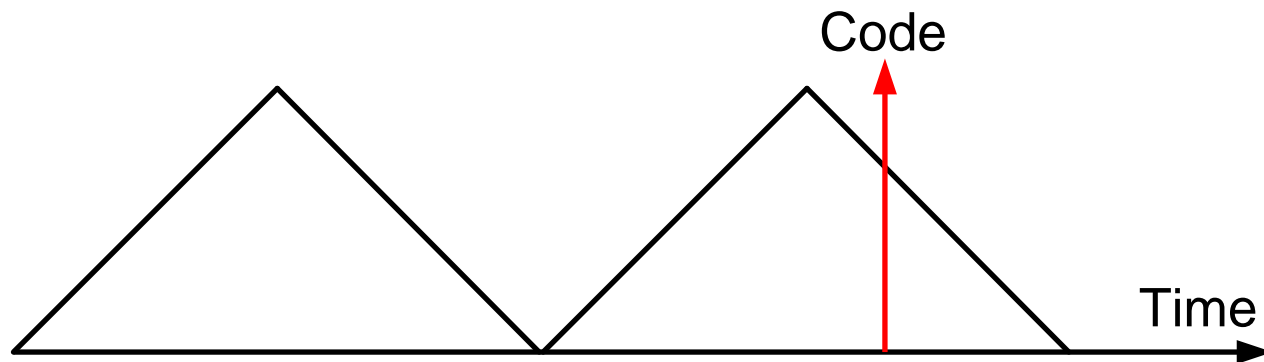
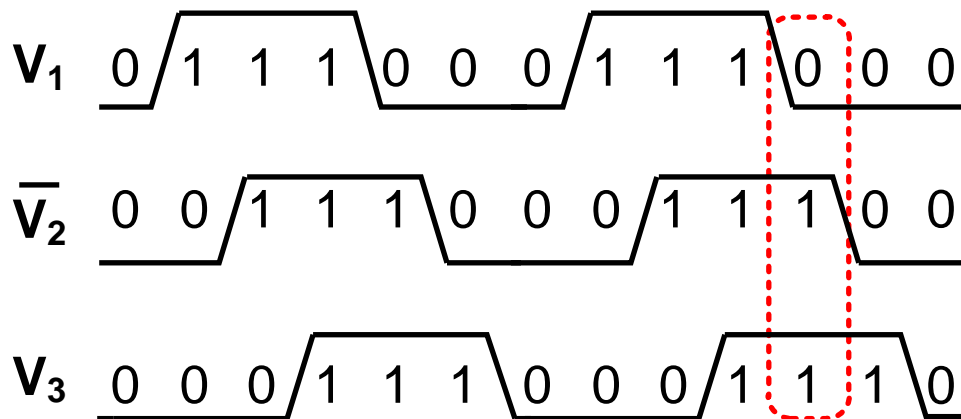
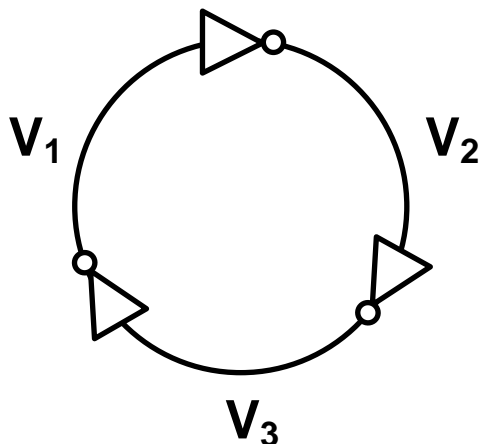
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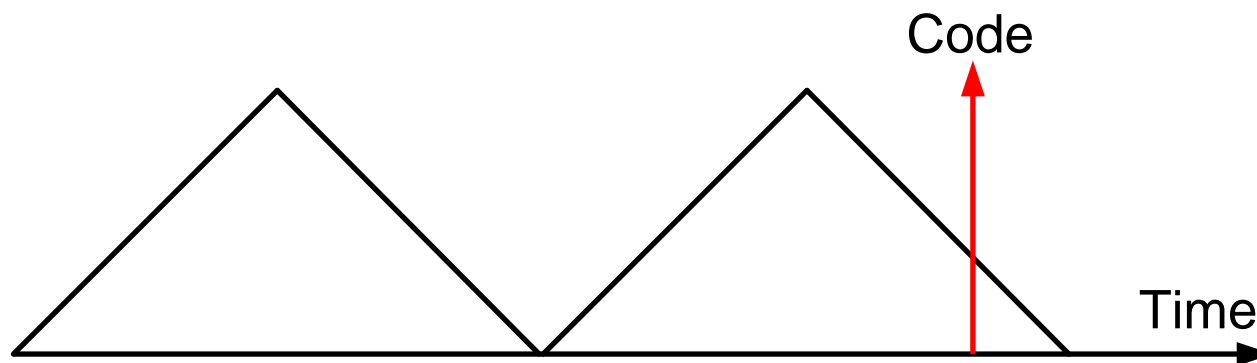
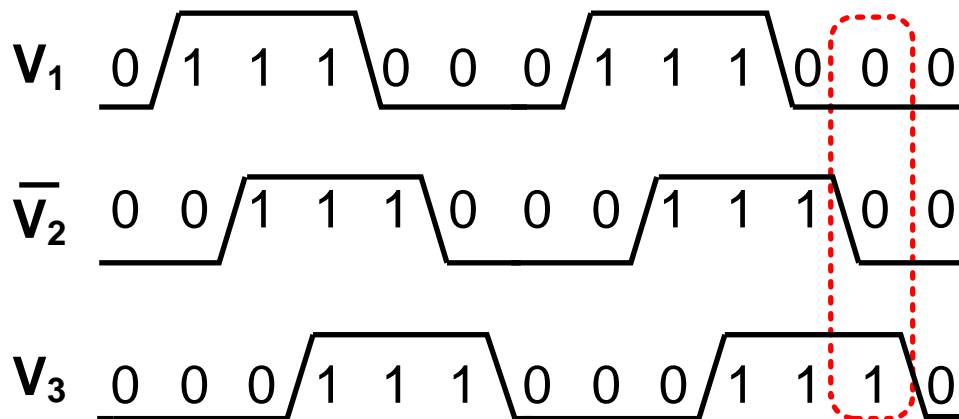
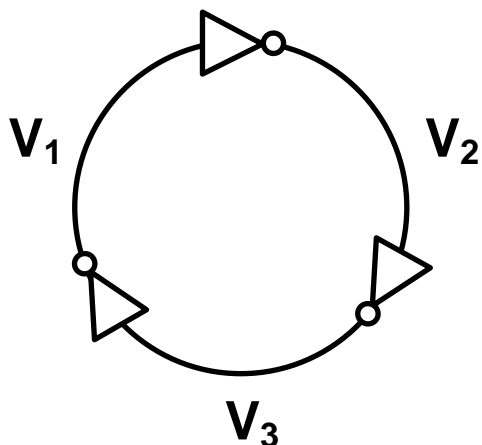
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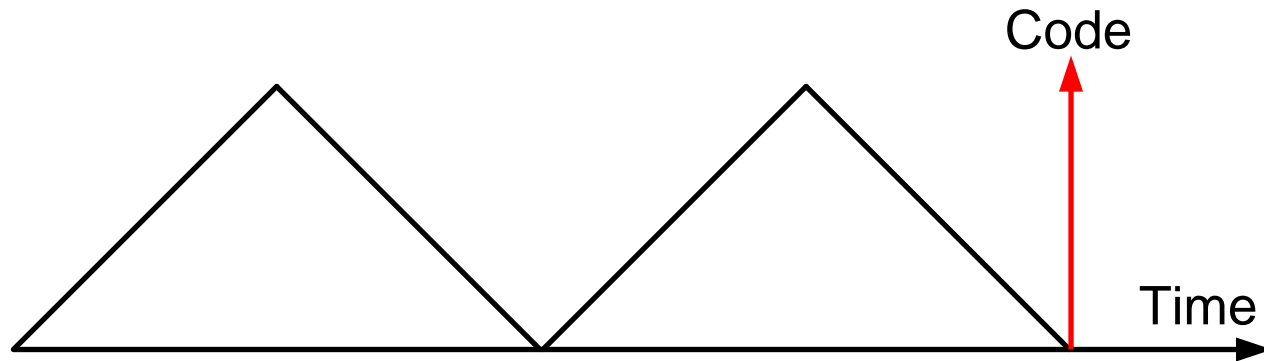
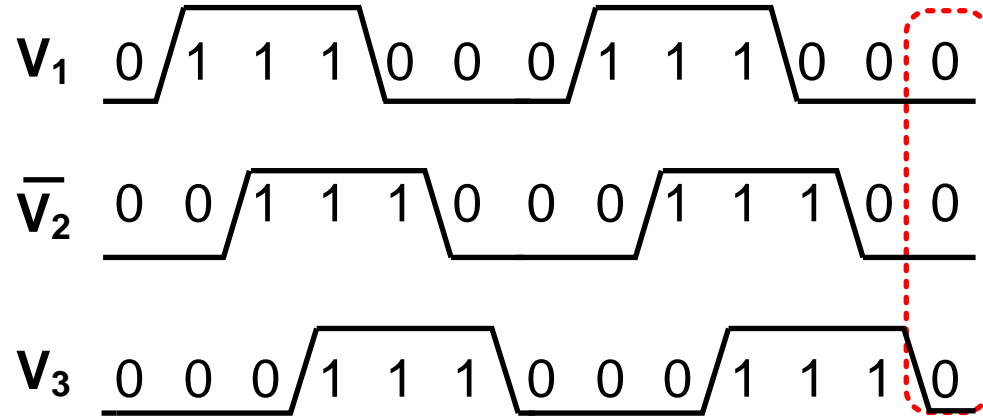
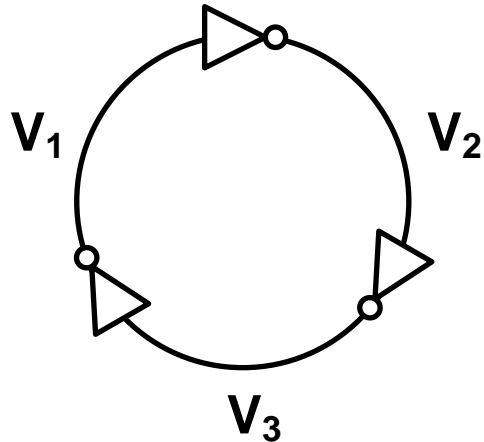
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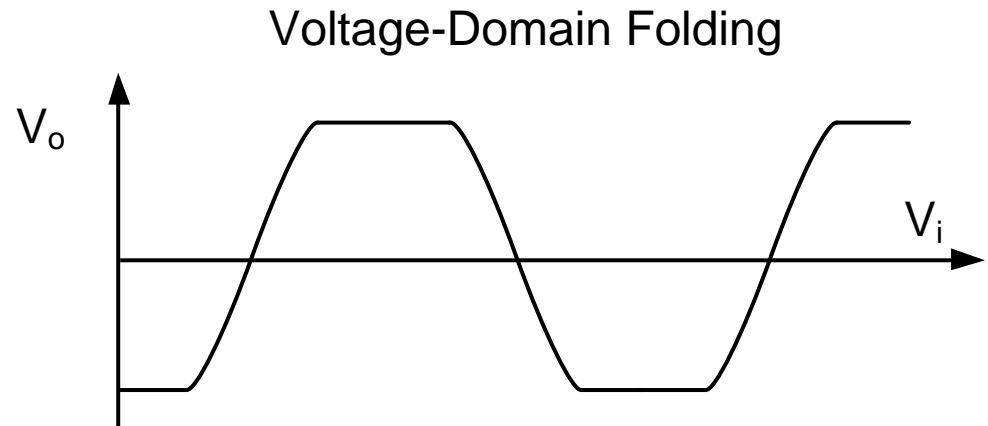
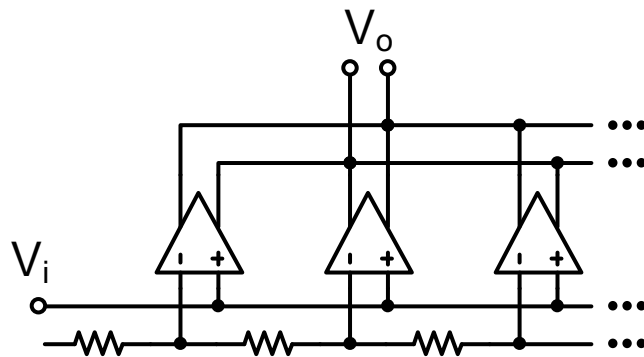
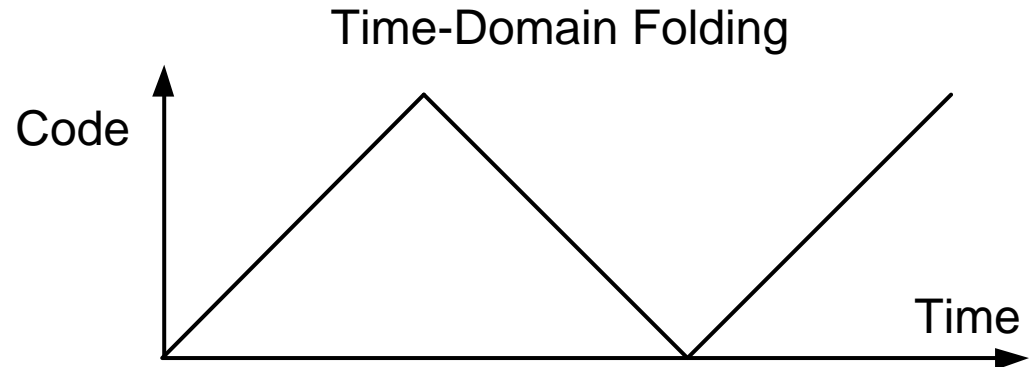
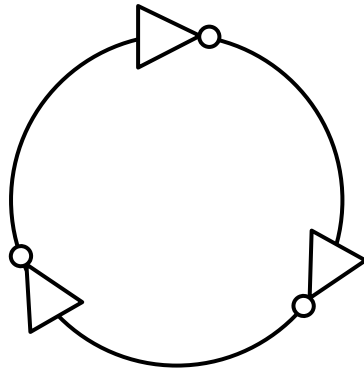
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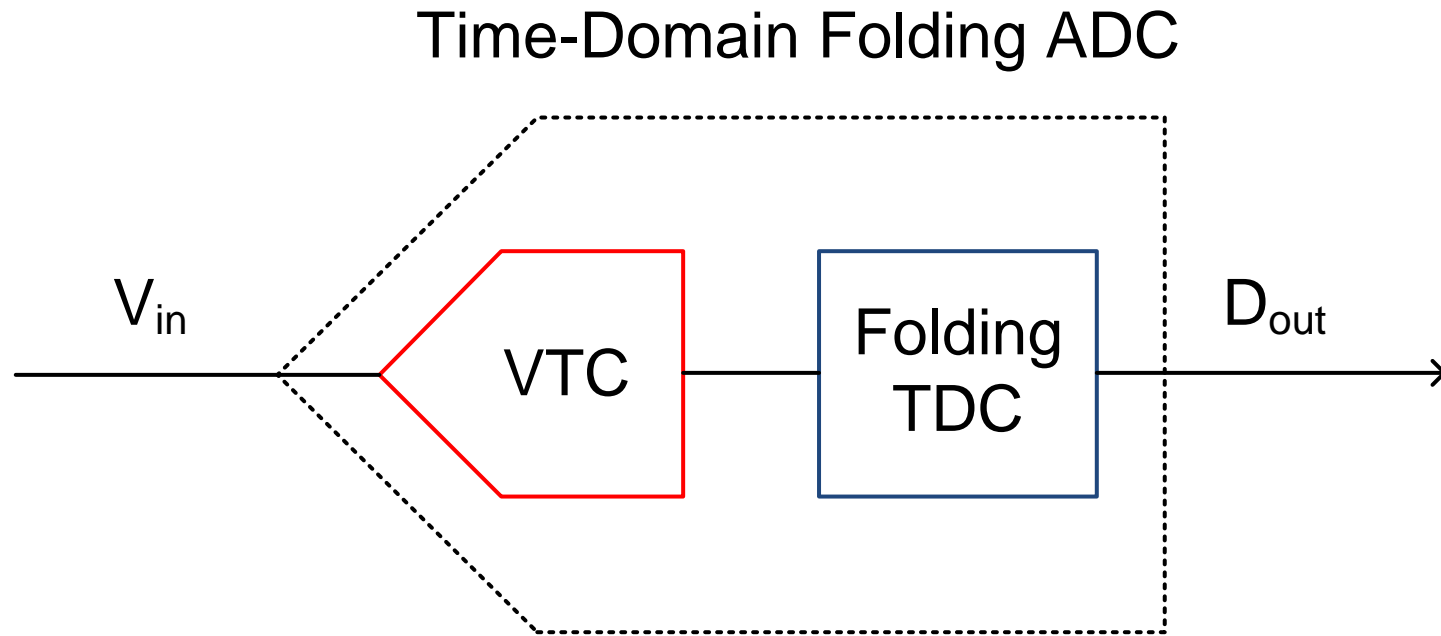
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Time-Domain vs. Voltage-Domain Folding



- Time-domain folding – linear, indefinite folding factor
- Voltage-domain folding – nonlinear, limited folding factor

Time-Domain Folding ADC

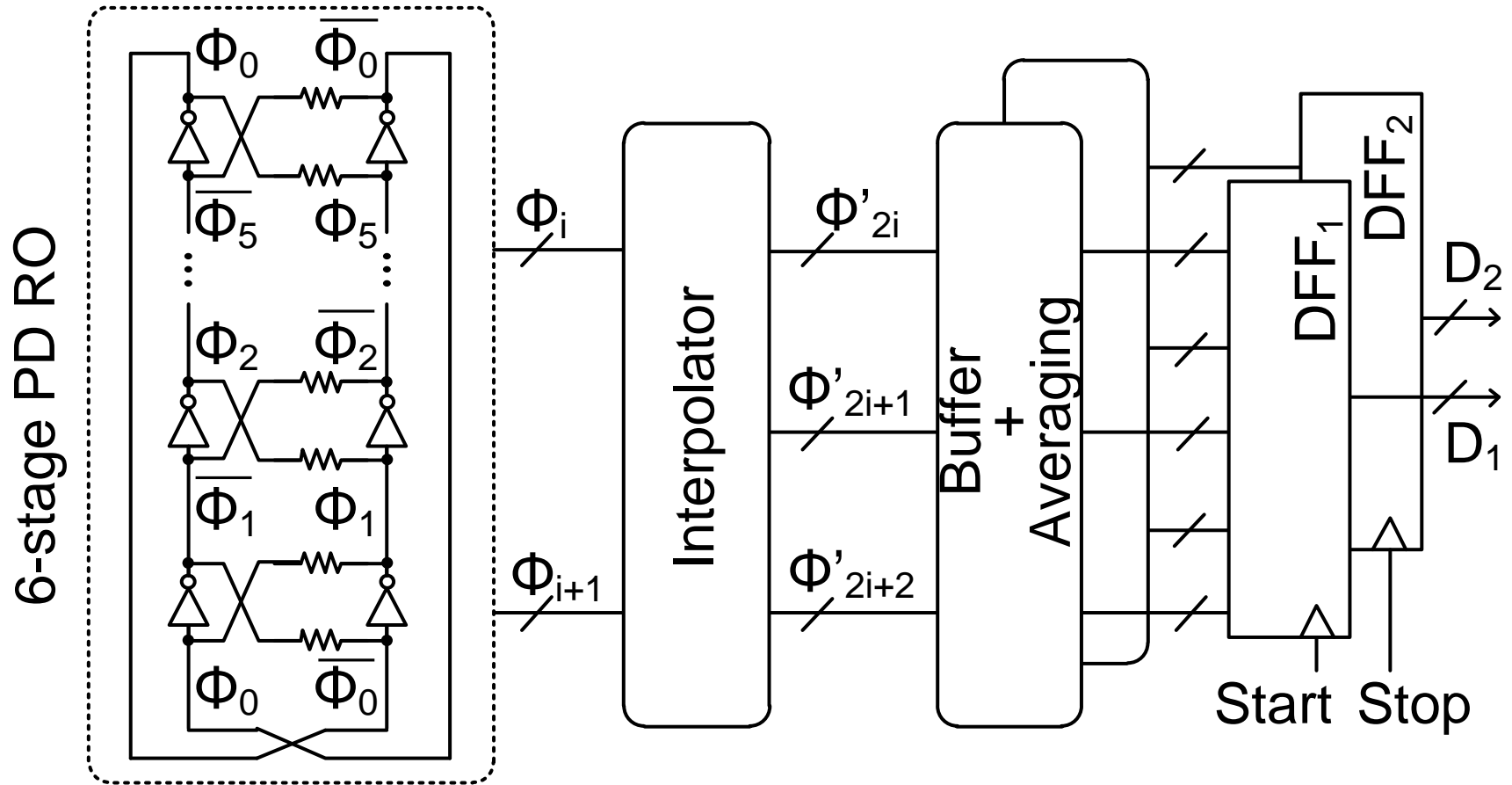


Targeting performance – 10 GS/s, 6 bits

Outline

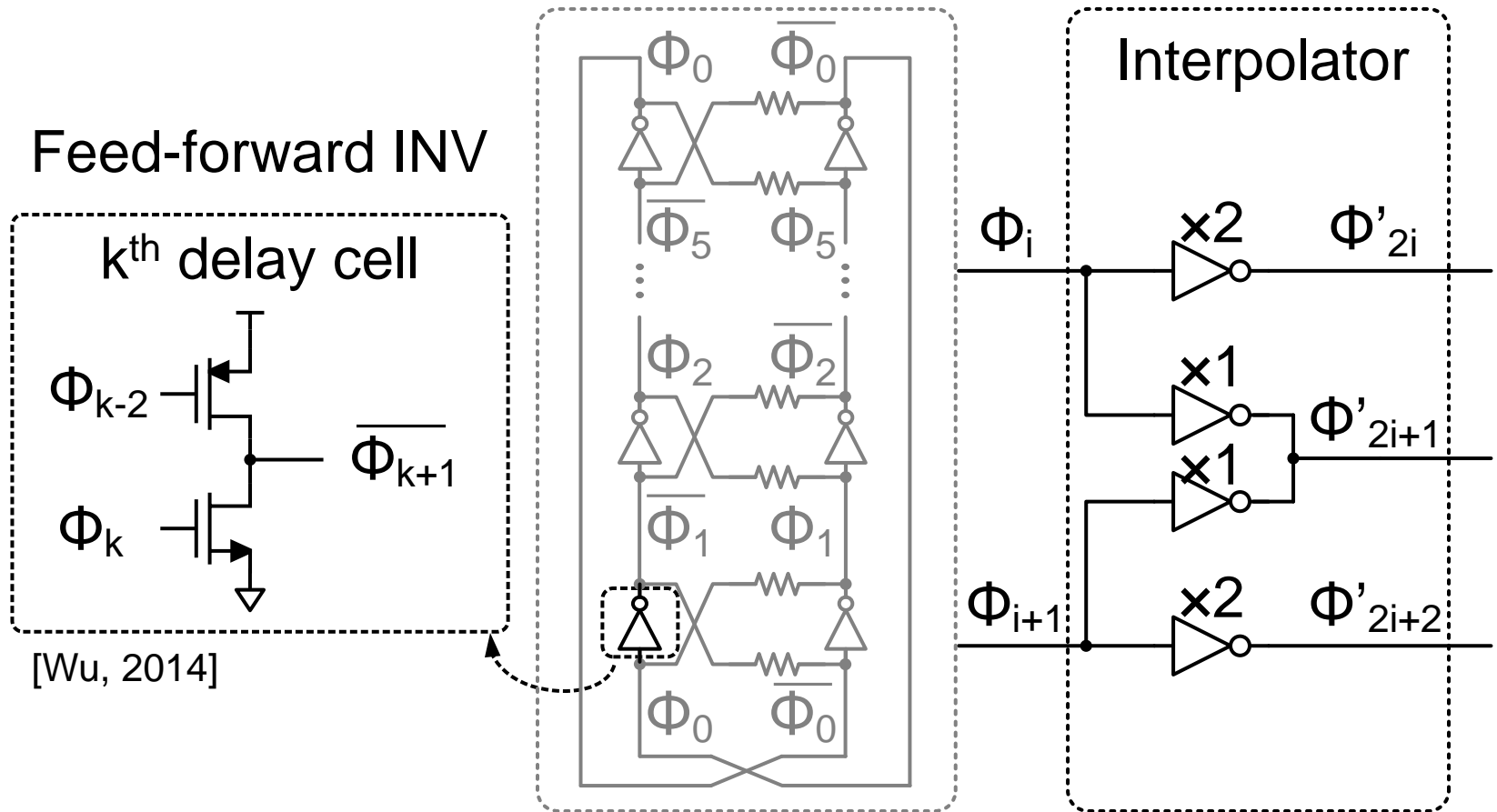
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RO-Based TDC



6-stage pseudo-diff. RO { common-mode rejection \uparrow
 delay uniformity \uparrow , DNL \uparrow

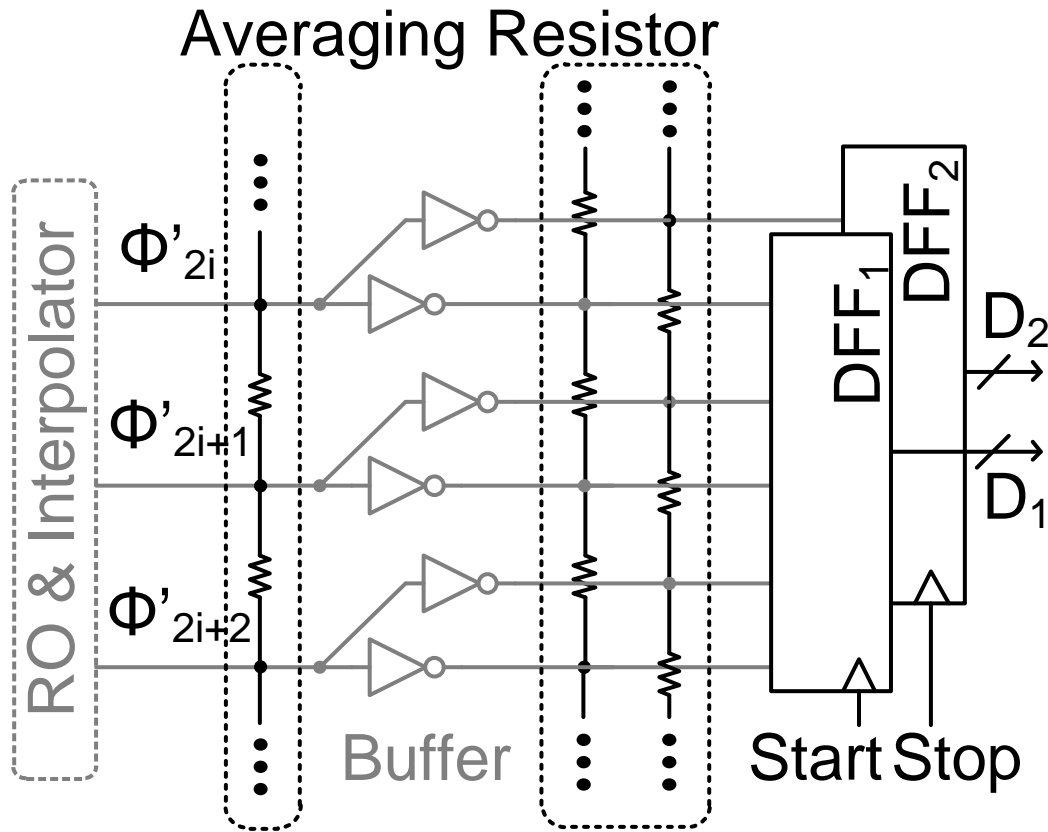
Speed-Up Techniques



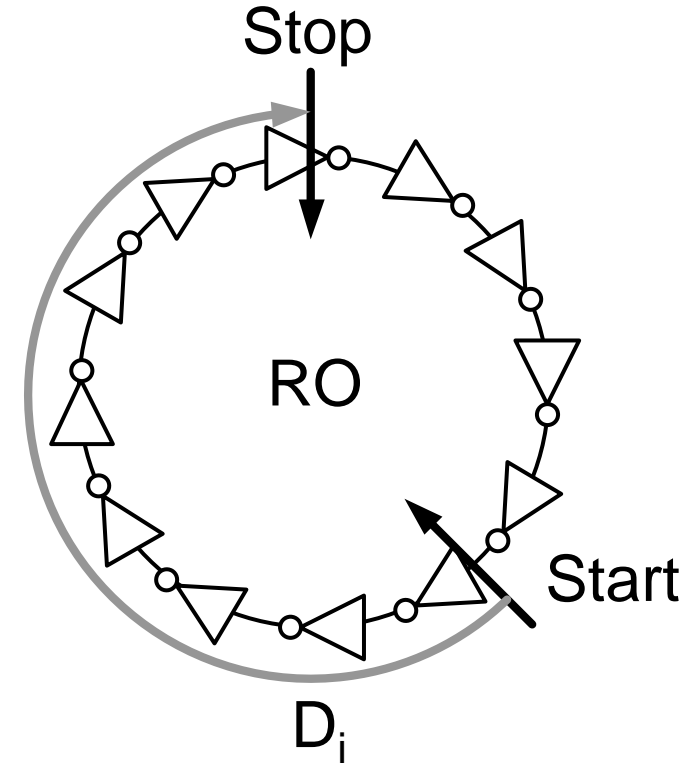
- Feed-forward
- $2 \times$ Interpolation

$$\left. \begin{array}{l} \text{Feed-forward} \\ \text{2} \times \text{Interpolation} \end{array} \right\} \text{LSB} = \frac{\text{inv.delay (65 nm CMOS)}}{4} = \frac{16 \text{ ps}}{4} = 4 \text{ ps}$$

Linearity Improvement Techniques

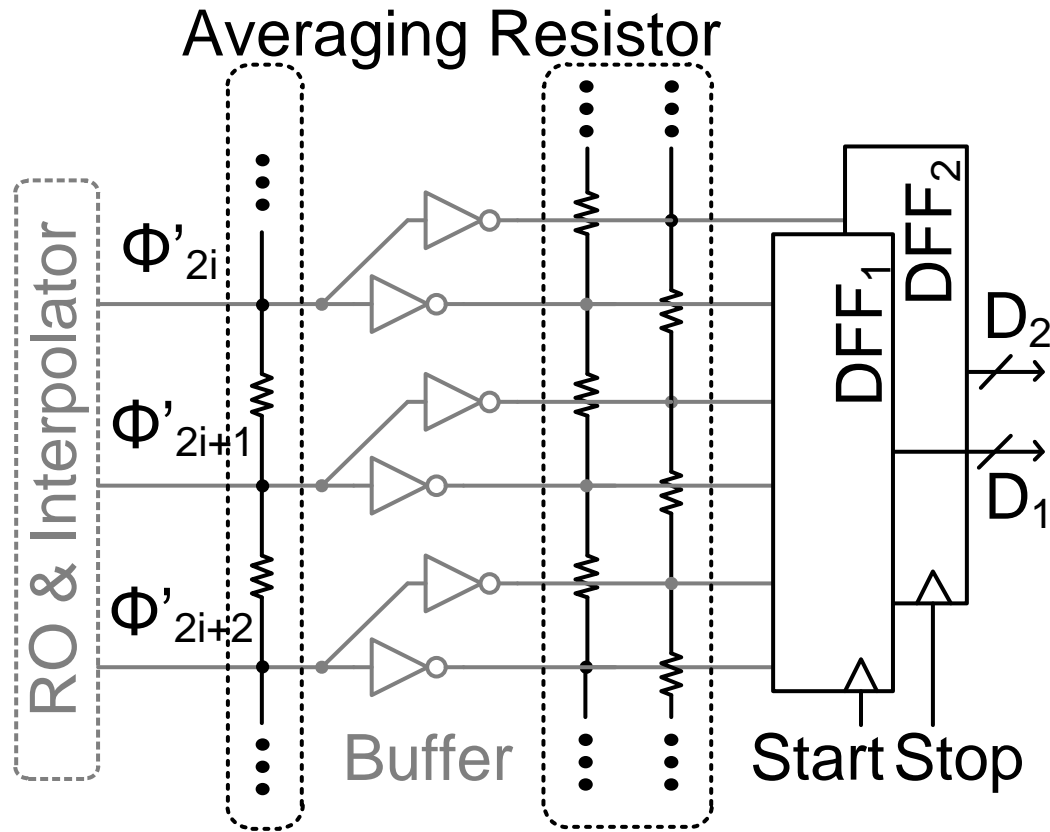


- Pseudo-diff. RO
 - Resistor averaging
 - Inherent DEM
- } linearity \uparrow

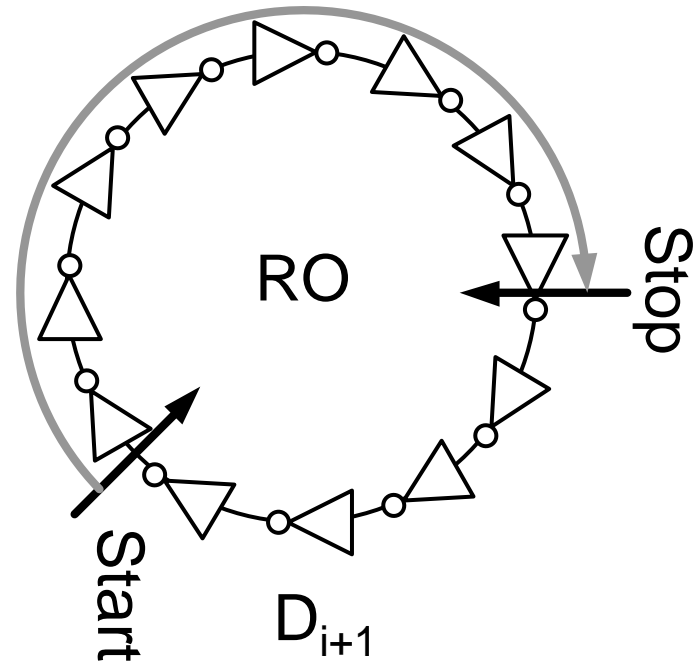


- Double Sampling
- ✓ inherent DEM
 - ✗ 3 dB SNR penalty [Wu, 2014]

Linearity Improvement Techniques

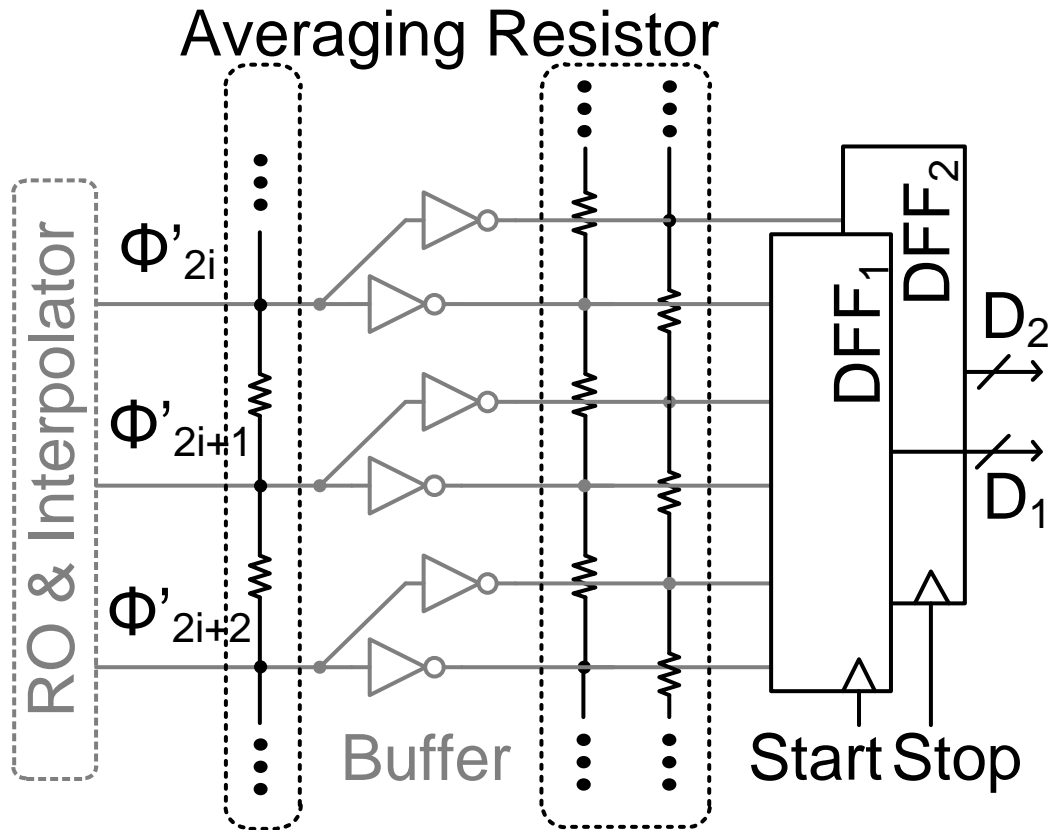


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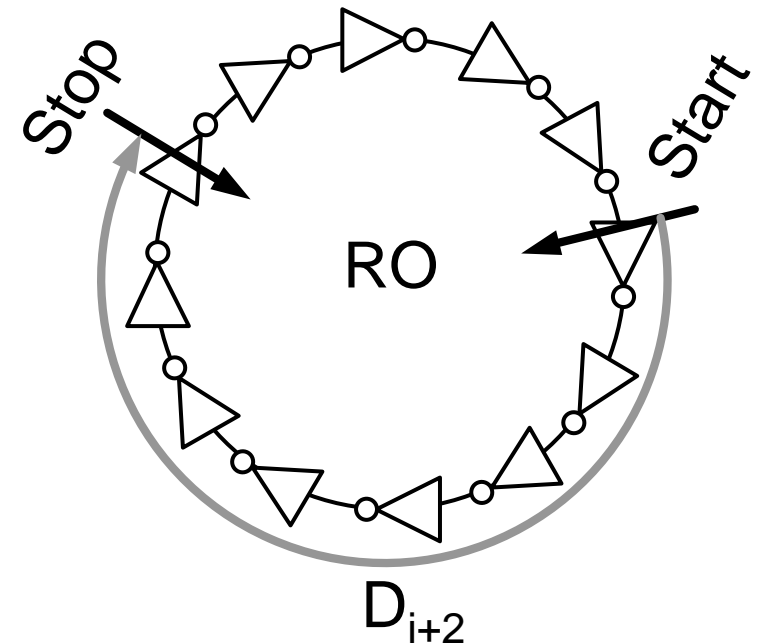


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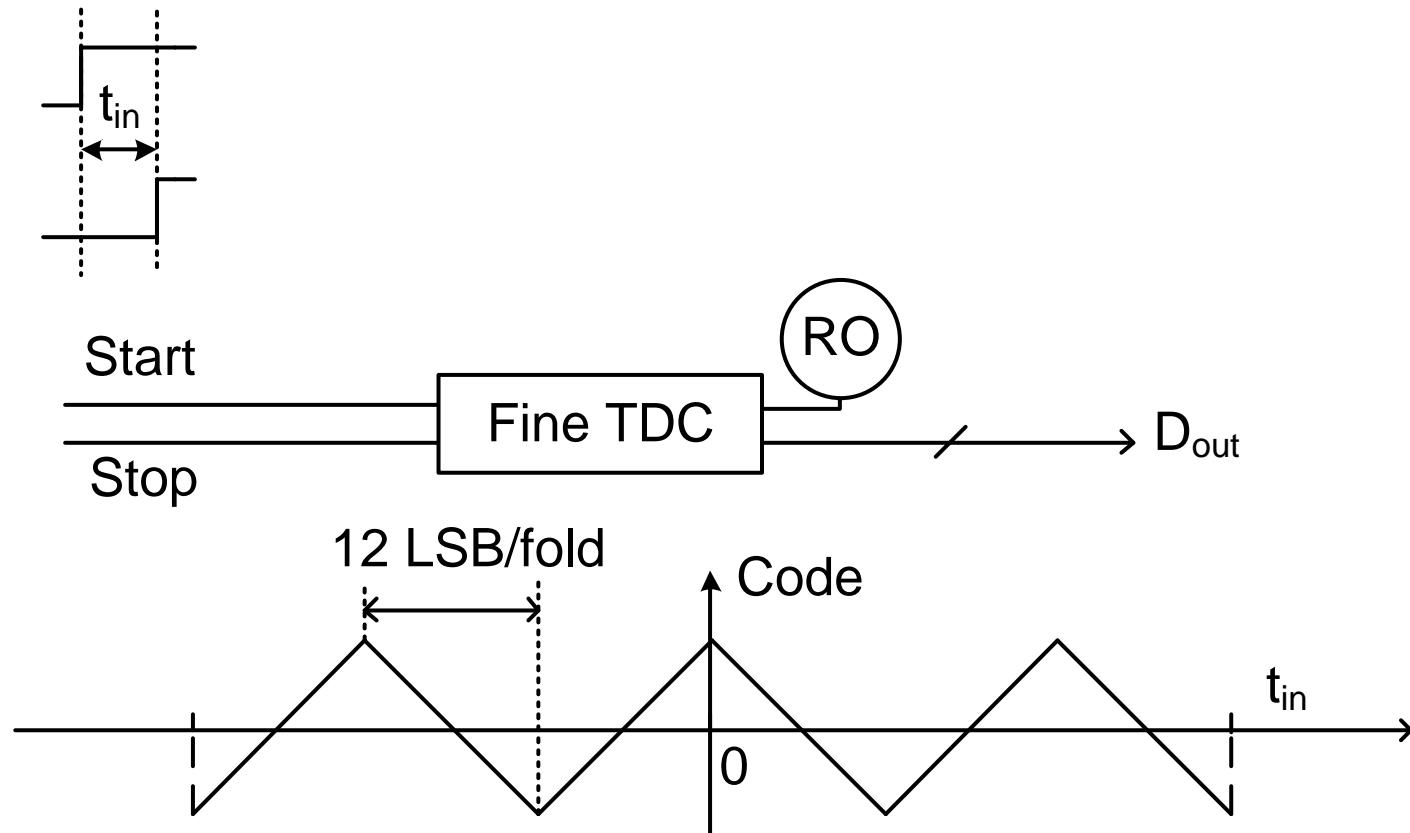


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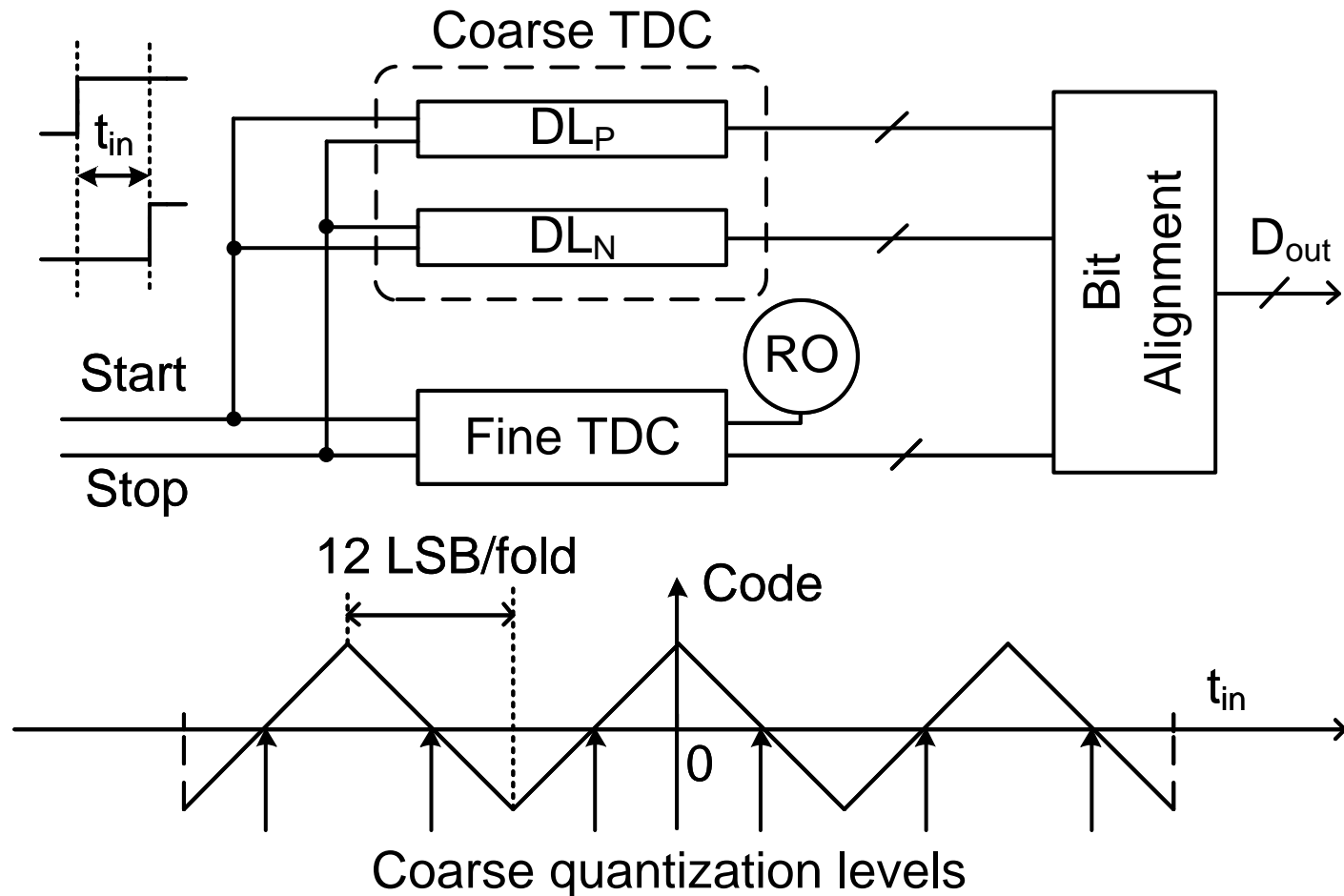
- Double Sampling
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Overall TDC Diagram



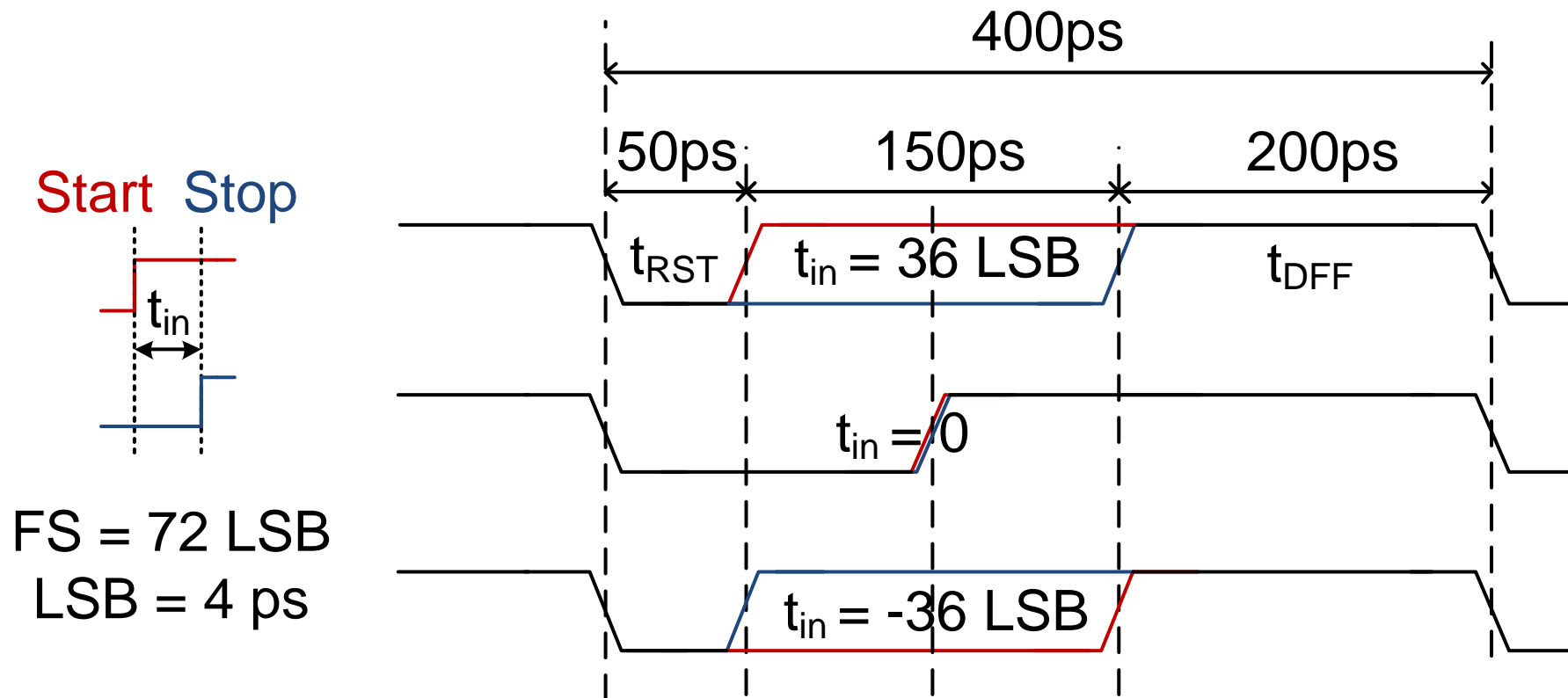
- 12 LSB/fold x 6 folds = 72 levels \rightarrow 6.2 bits
- Coarse TDC – folded differential DL [Stephan, 2010]

Overall TDC Diagram



- 12 LSB/fold x 6 folds = 72 levels \rightarrow 6.2 bits
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Simplified TDC Timing Diagram

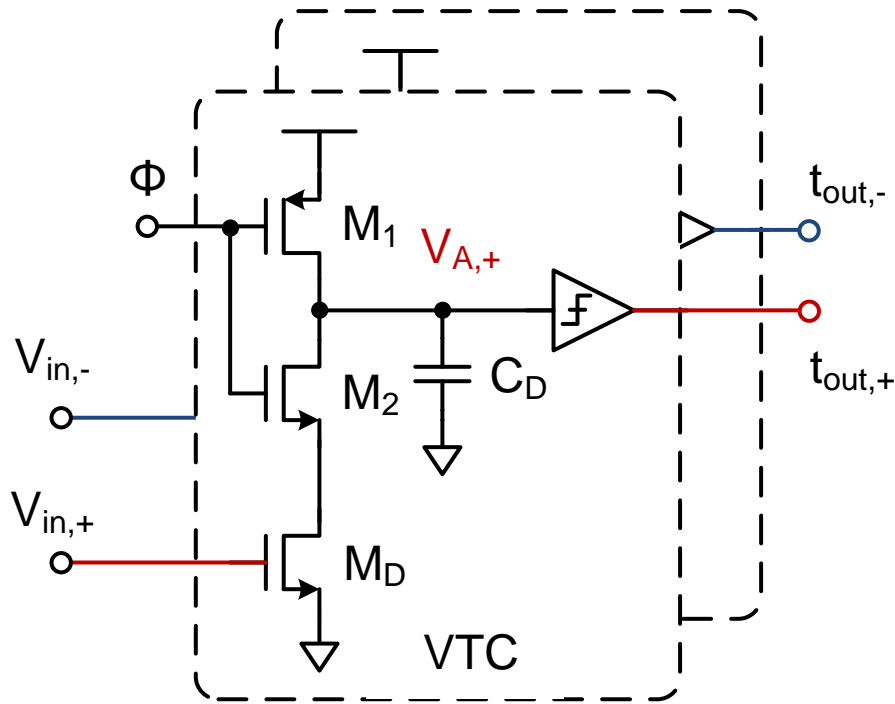


- $t_{in} \text{ span} = \pm 150\text{ps} \approx \pm 36 \text{ LSBs}$
- $T_{TDC} = t_{RST} + t_{in} + t_{DFF} = 400 \text{ ps} \rightarrow \text{Max. speed is } 2.5 \text{ GS/s}$

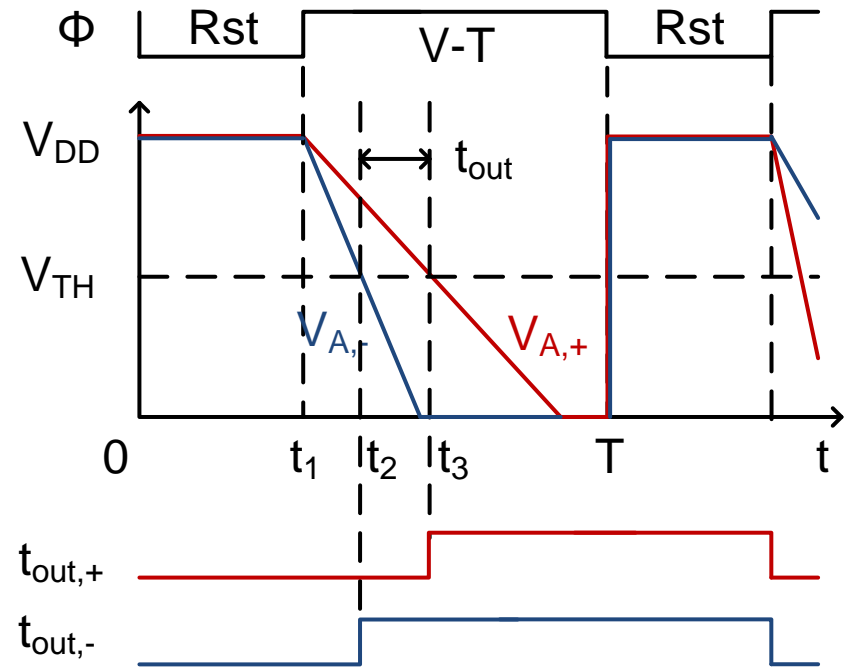
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Current-Starved Inverter (CSI) Based VTC

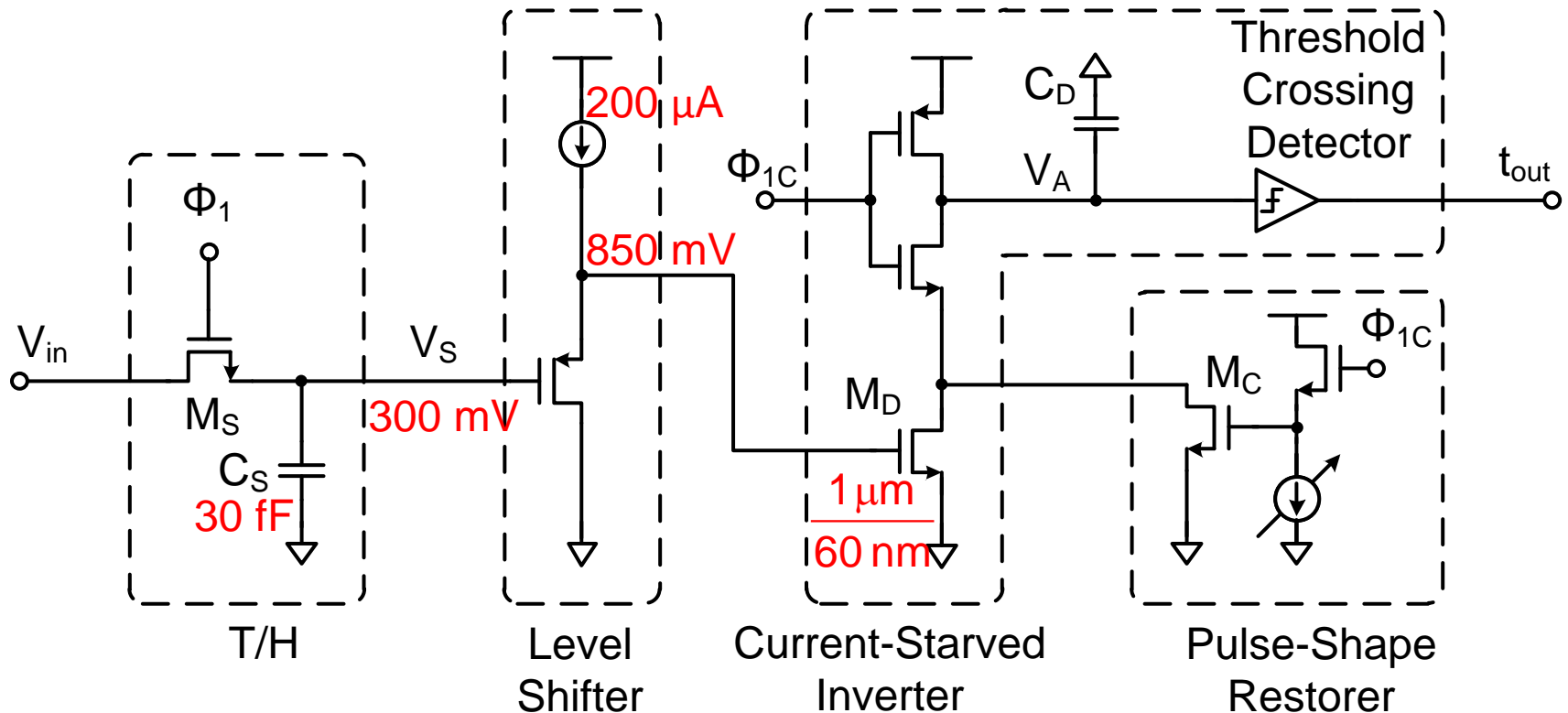


[Macpherson, 2013]



- The discharge current is controlled by V_{in}
- Pseudo-diff. structure improves linearity

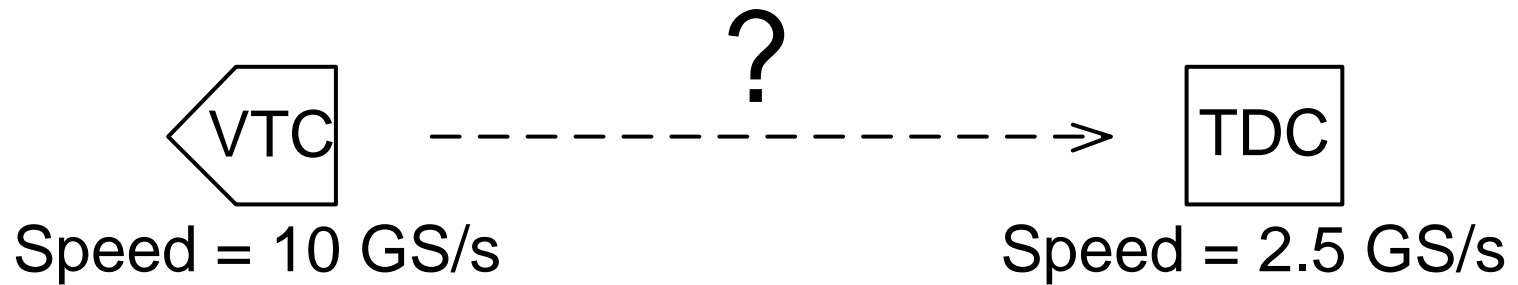
Overall VTC Schematic



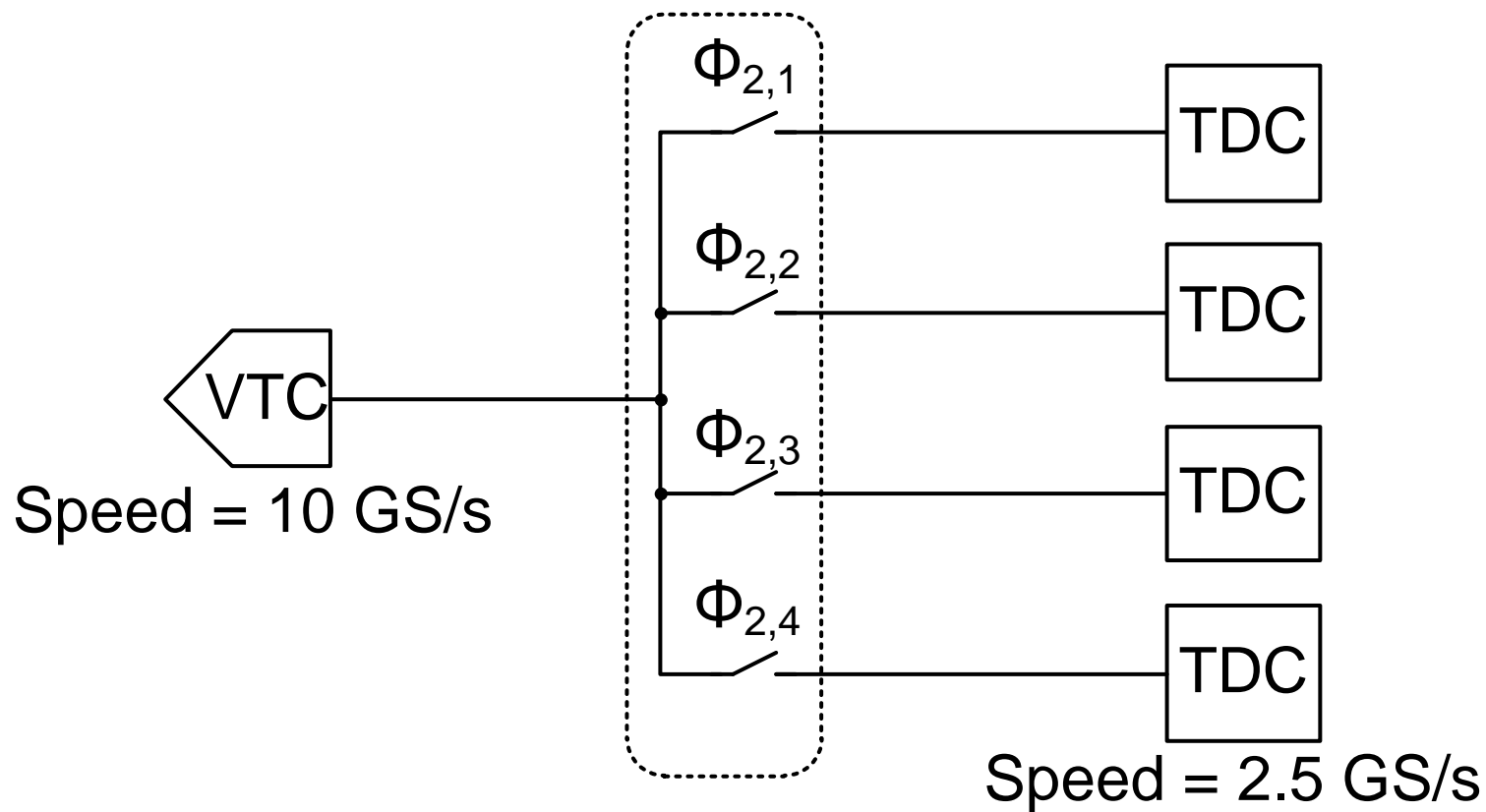
Simulation shows:

- Speed = 10 GS/s, linearity ≥ 6 bits
- Output range $\sim \pm 20$ ps ($T/2 = 50$ ps)

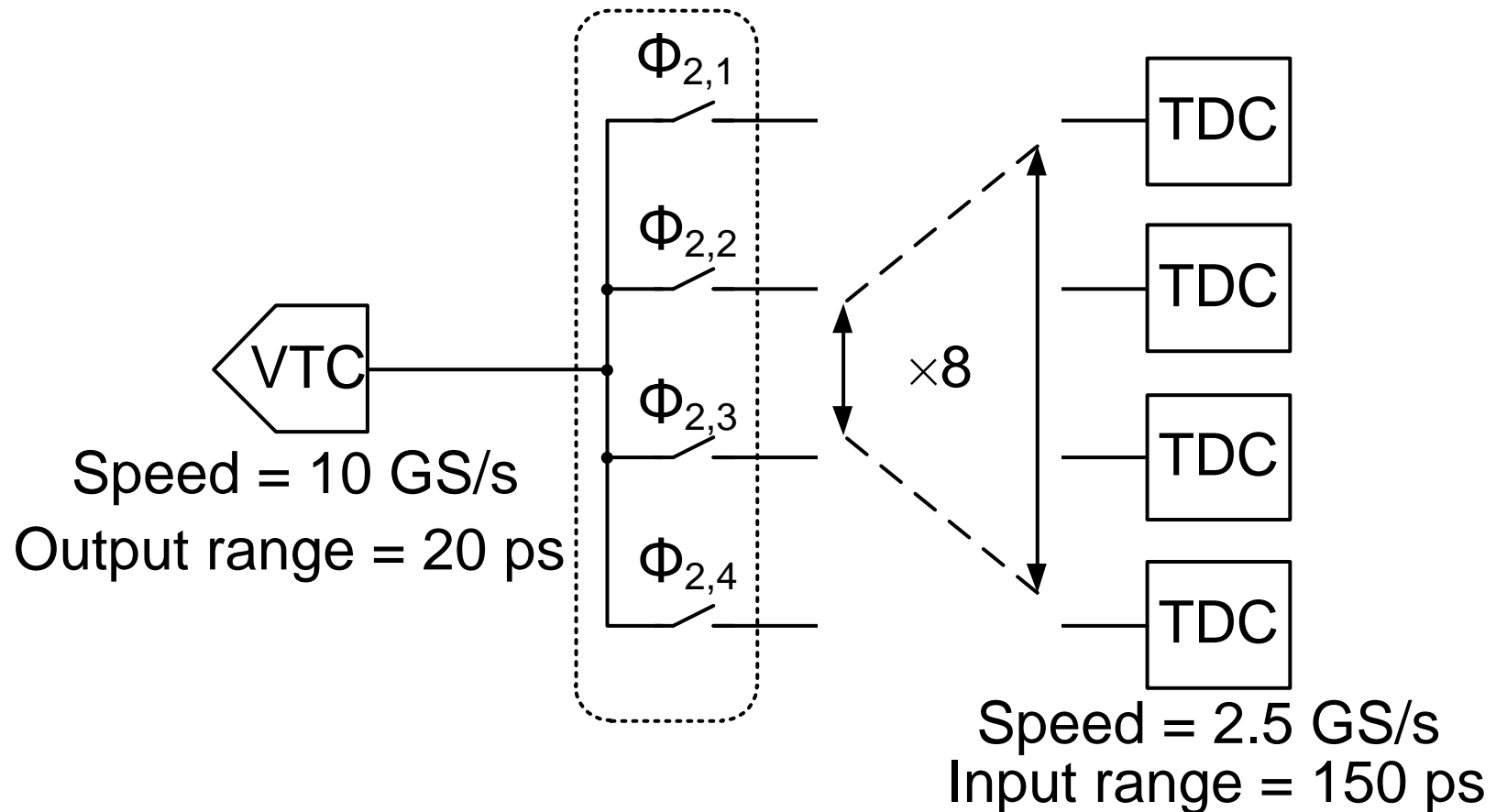
ADC (VTC + TDC) Architecture



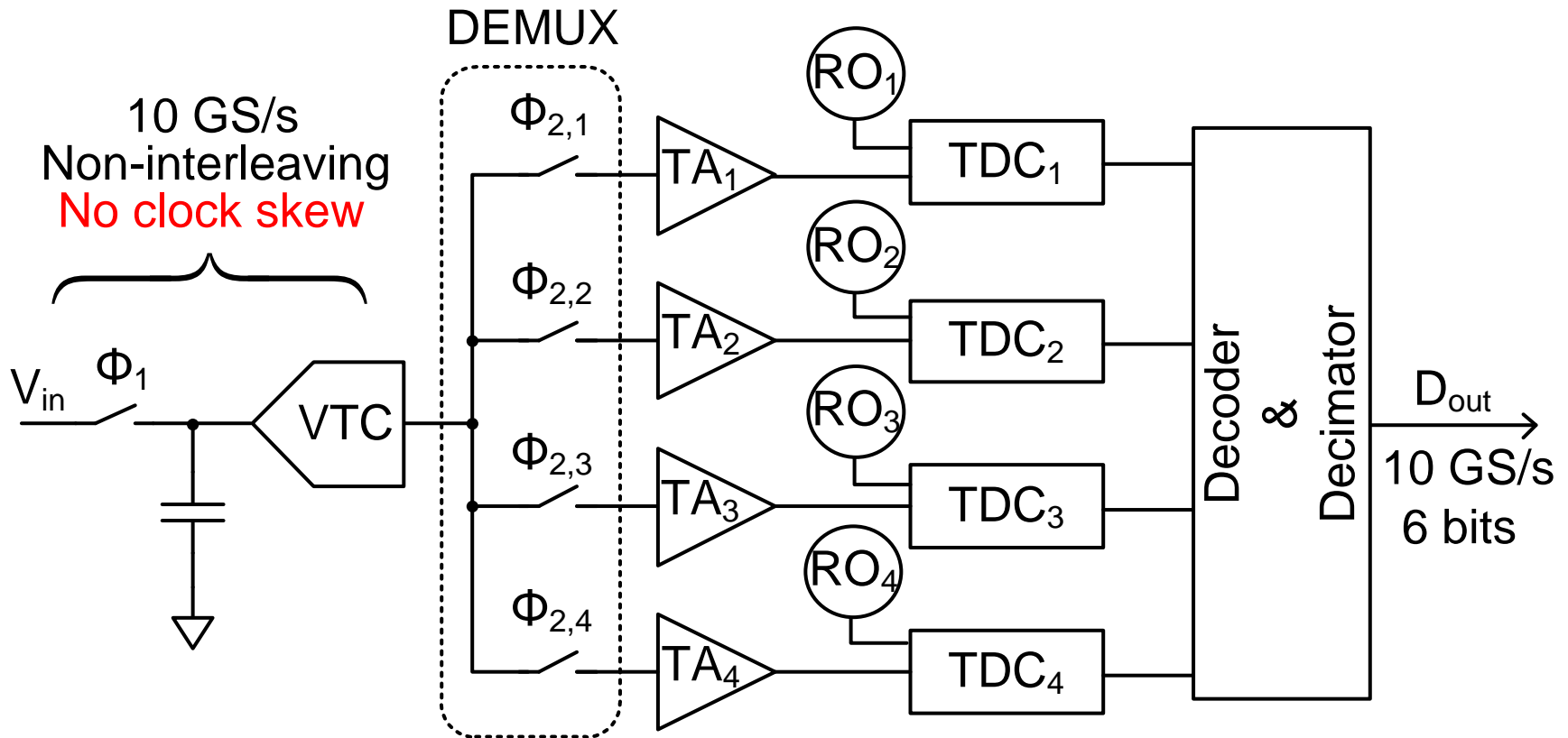
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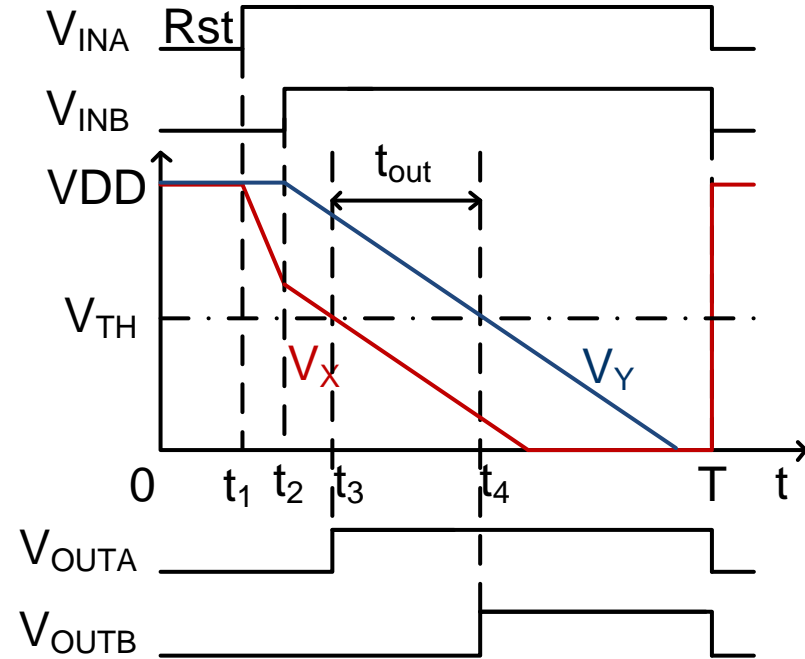
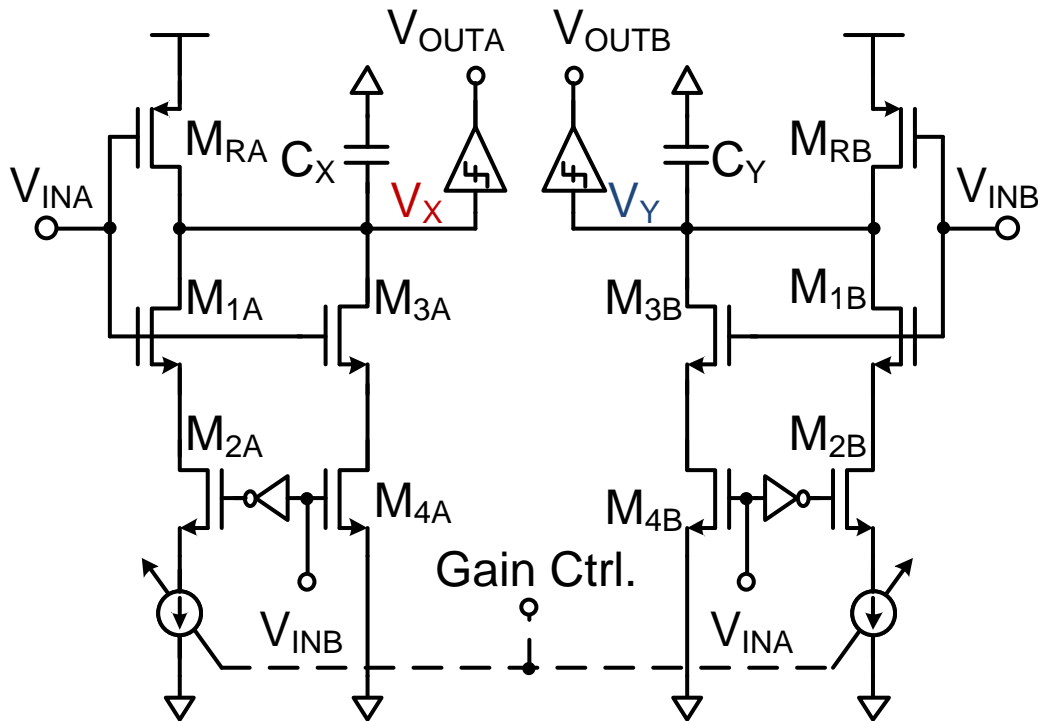


- Single VTC frontend at 10 GS/s
- 4 interleaved TDCs at 2.5 GS/s

Outline

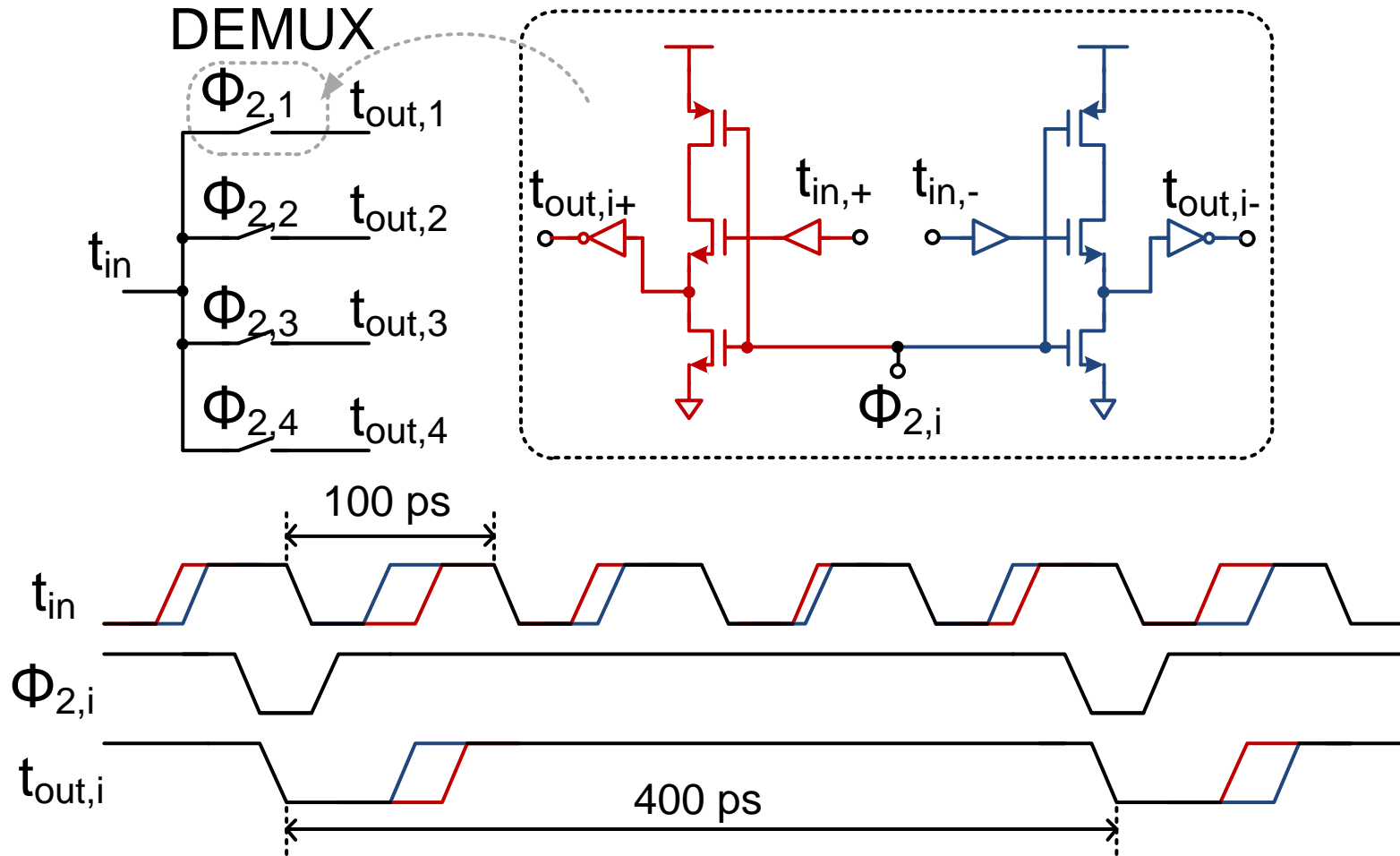
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Time Amplifier



- Double-rate discharging TA [Hye-Jung, 2011]
- Gain = slope ratio between discharging steps
- Gain calibrated with 4-bit DAC

DEMUX

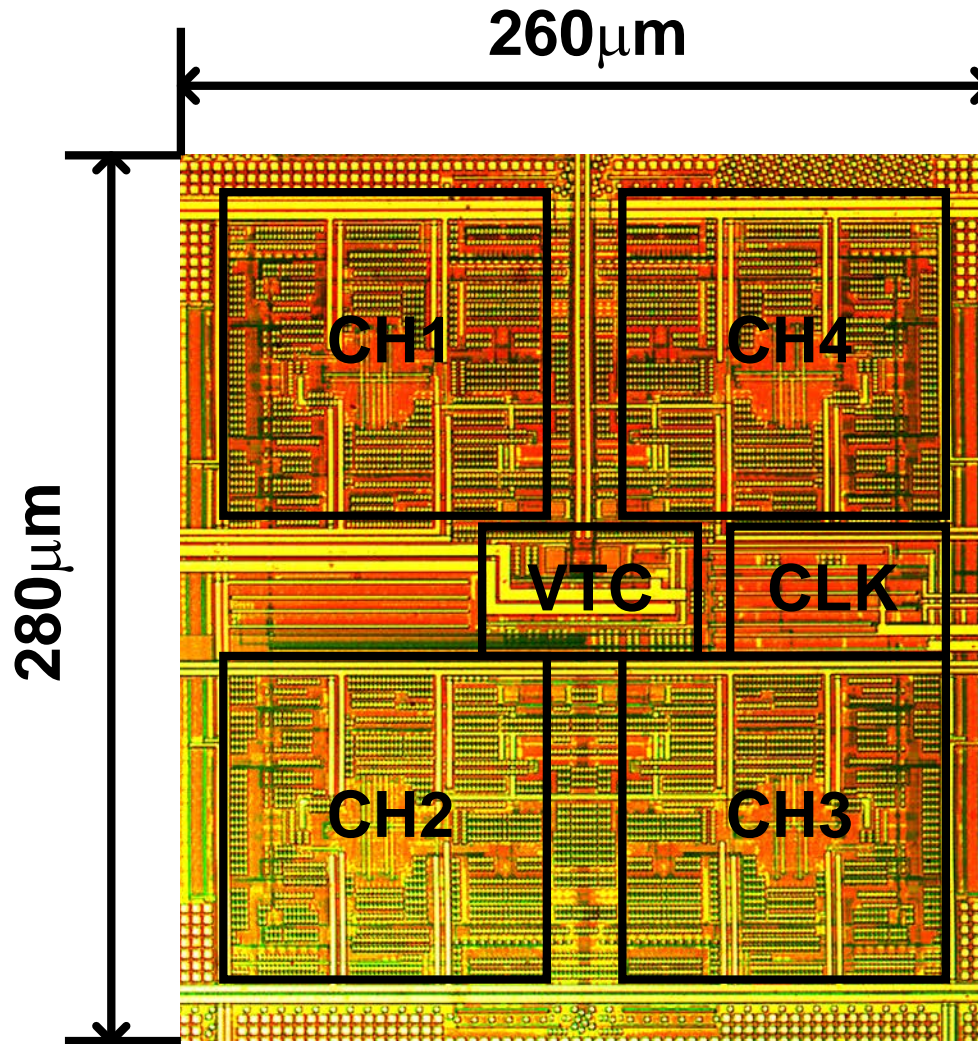


- Dyn. INV based DEMUX only passes rising edges

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Die Photo

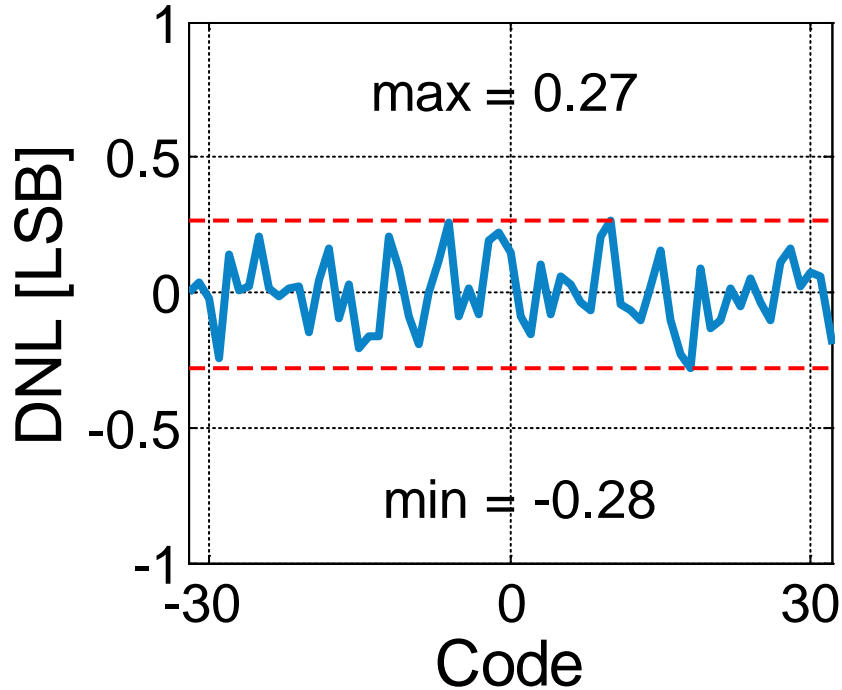


65nm LPE CMOS

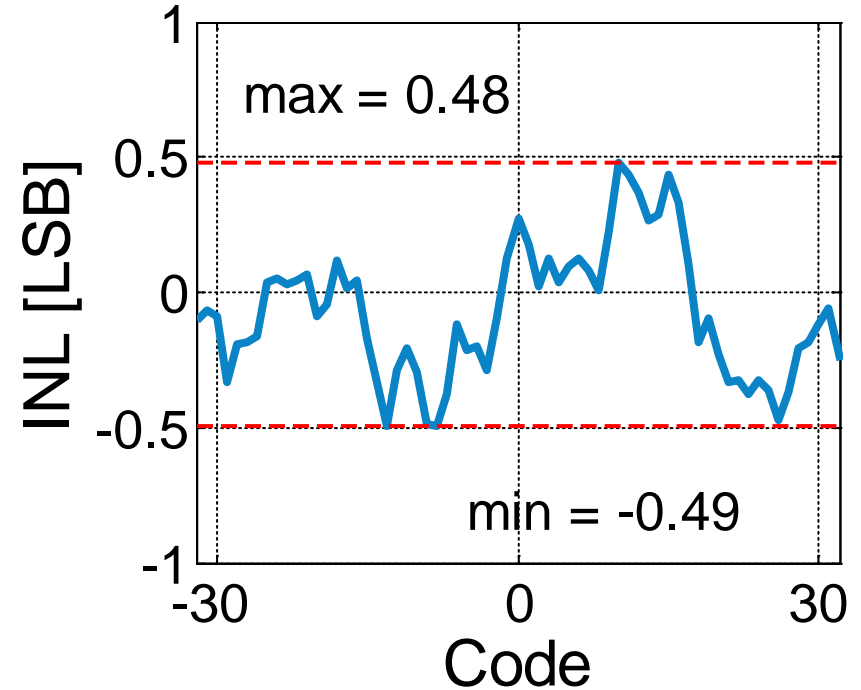
Area = 0.073 mm²

Measured DNL and INL

DNL < 0.3 LSB

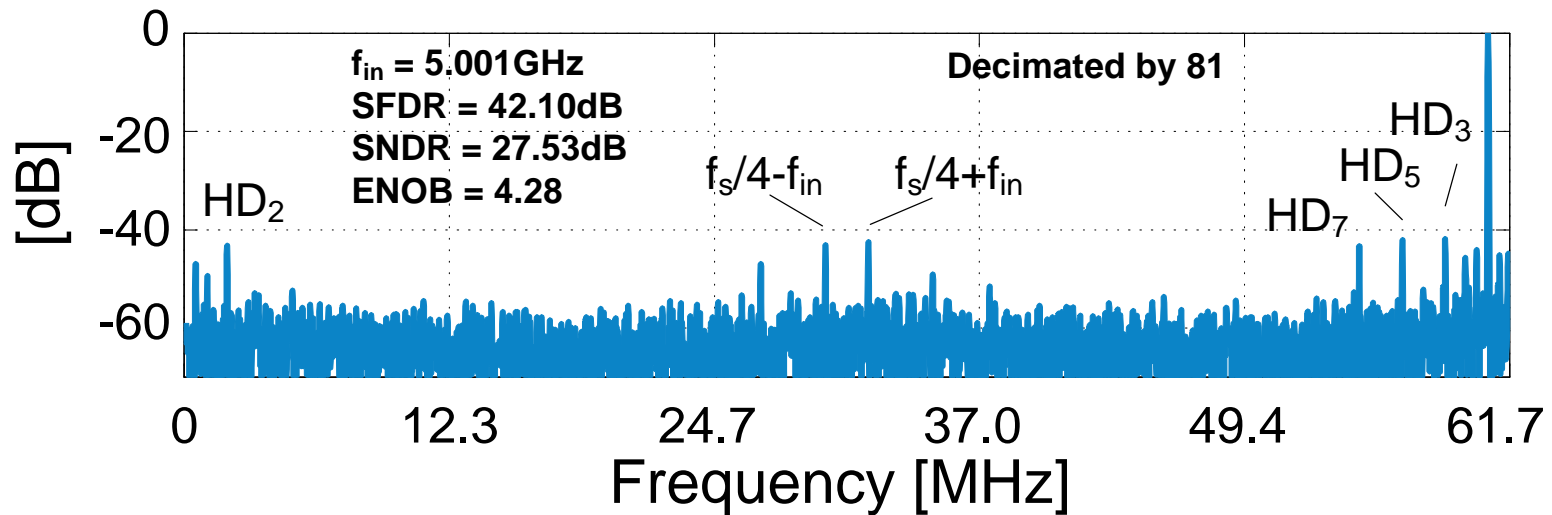
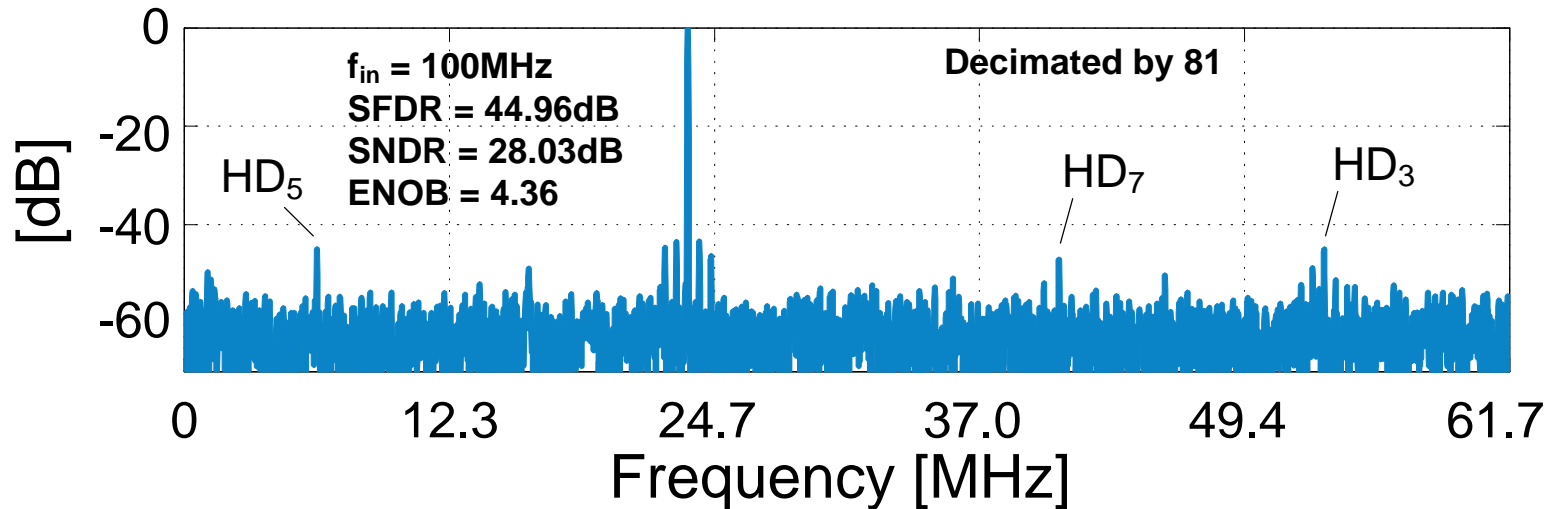


INL < 0.5 LSB

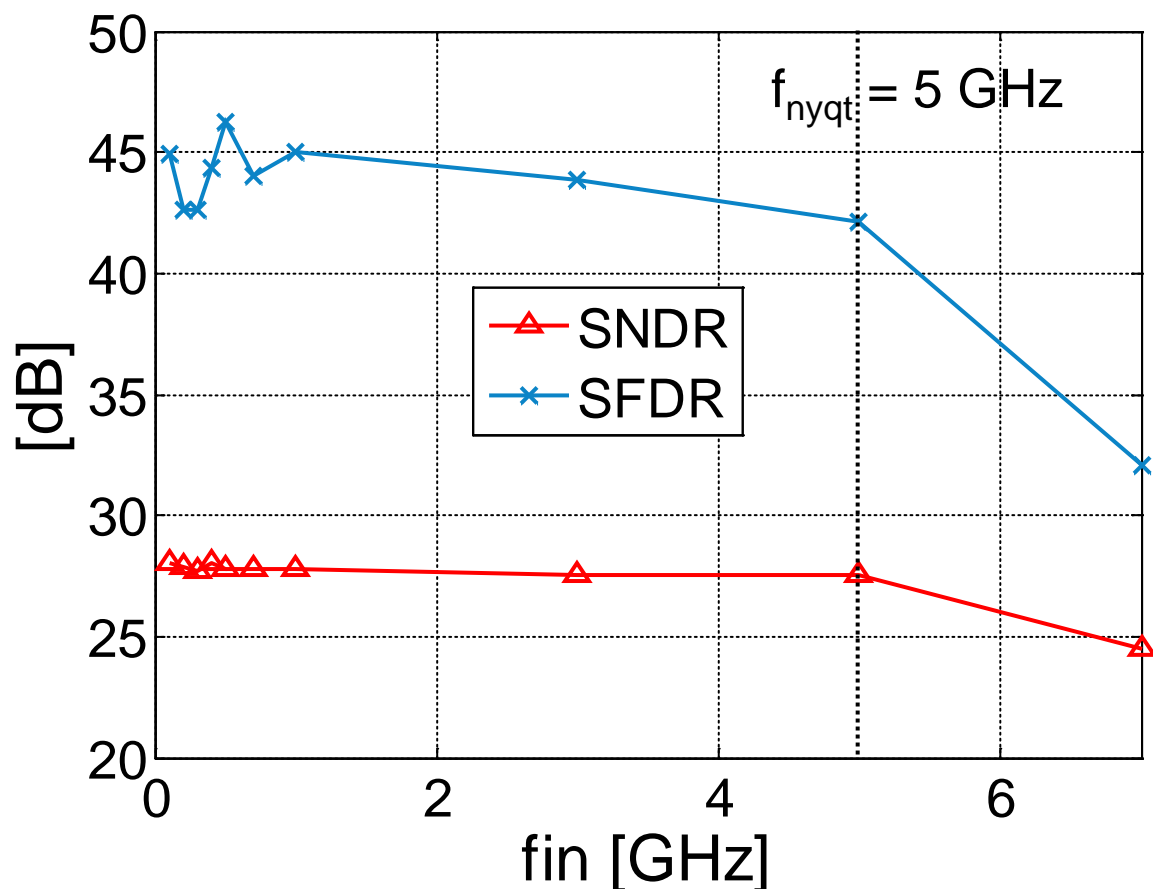


Test Conditions: $V_{DD} = 1.3 \text{ V}$, $f_s = 10 \text{ GS/s}$

Measured Output Spectra

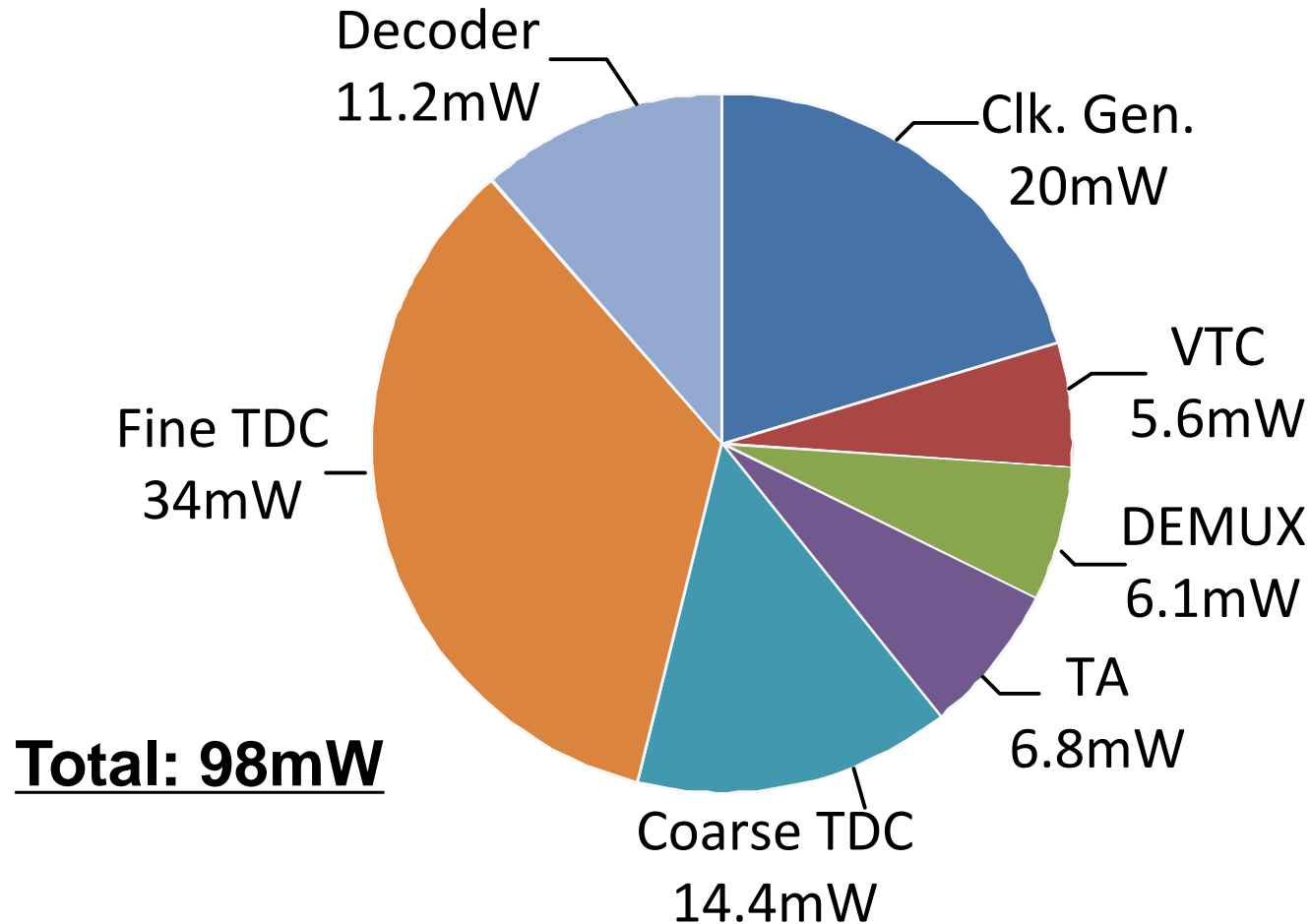


Measured Dynamic Performance



Test Conditions: $V_{DD} = 1.3$ V, $f_s = 10$ GS/s

ADC Power Breakdown



Test Conditions: $V_{DD} = 1.3 \text{ V}$, $f_s = 10 \text{ GS/s}$

Performance Comparison

	This work	CICC' 13 [4]	VLSI' 13 [1]	ISSCC' 13 [3]	ISSCC' 14 [3]
Architecture	Time Domain	Time Domain	TI SAR	TI Flash	TI Flash
Tech. (nm)	65	65	65	40	32 SOI
f_s (GS/s)	10	5	10	10.3	20
ENOB@Nyq. (bits)	4.3	2.8	4.0	5.1	4.8
SNDR@Nyq. (dB)	27.2	18.4	26.0	33	30.7
SFDR@Nyq. (dB)	42.1	22.3	36	NA	39.4
DNL (LSBs)	0.28	0.91	0.19	NA	0.47
INL (LSBs)	0.49	0.95	0.65	NA	0.42
Power (mW)	98	35	79.1	240	69.5
Area (mm ²)	0.073	0.08	0.52	0.27	0.25
FoM (fJ/step)	504	1000	480	700	124

Outline

- Motivation for Time Domain
- Time to Digital Converter
- Voltage to Time Converter
- Other Circuits
- Measurement Results
- **Conclusion**

Conclusion

- A time-domain 10-GS/s, 6-bit folding flash ADC with high area efficiency is presented.
- The single VTC front-end requires no clock-skew calibration at 10 GS/s in 65-nm CMOS.
- The RO-based folding TDC achieves high area efficiency and high speed (2.5 GS/s) simultaneously.
- The inherent DEM of the RO-based TDC achieves excellent conversion linearity.

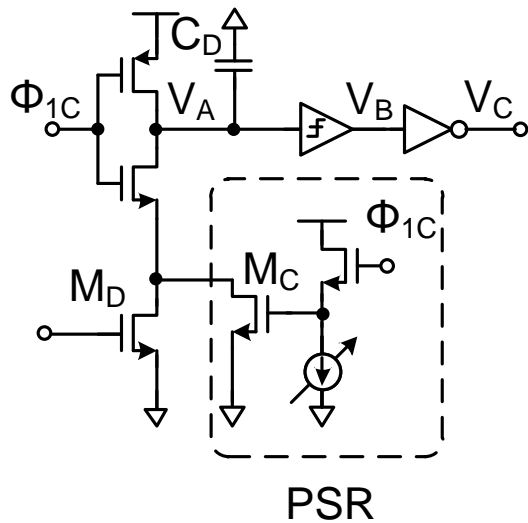
Acknowledgement

We thank SRC for the TxACE silicon fabrication program and Analog FastSPICE (AFS) Platform from Mentor Graphics.

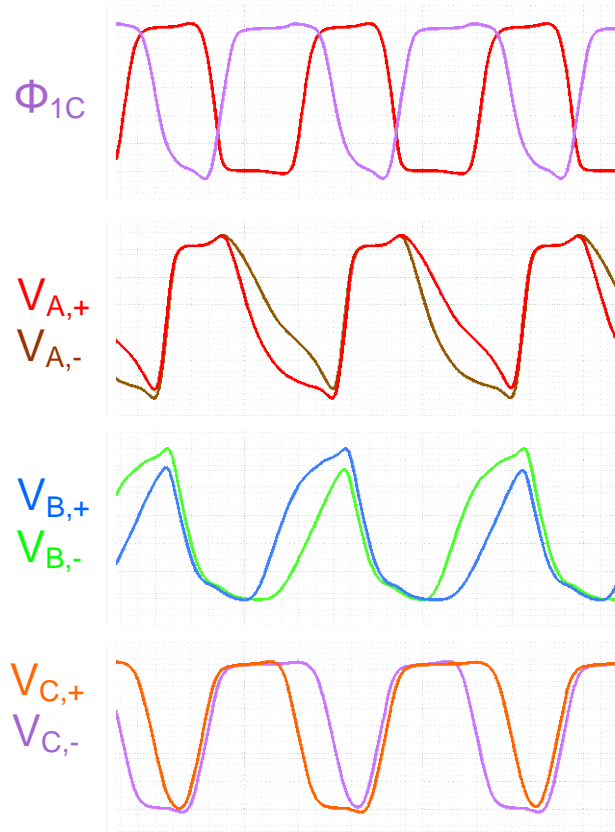
Thank you!

Backup slides

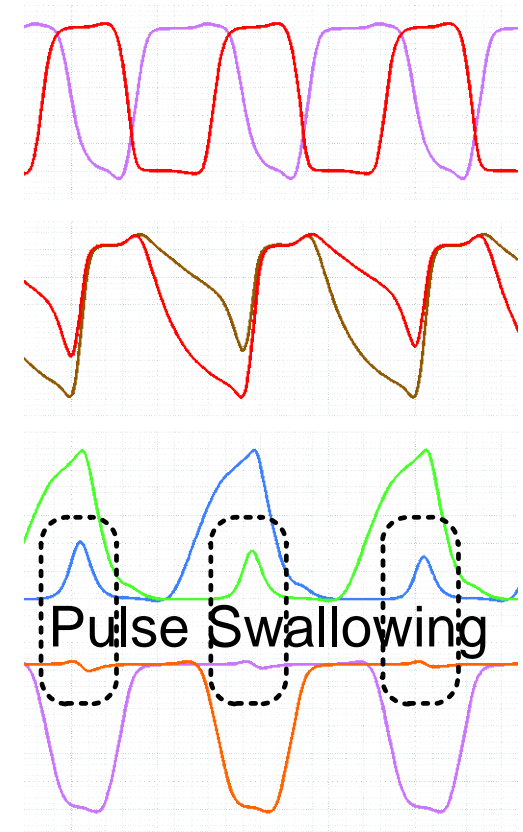
Pulse-Shape Restorer



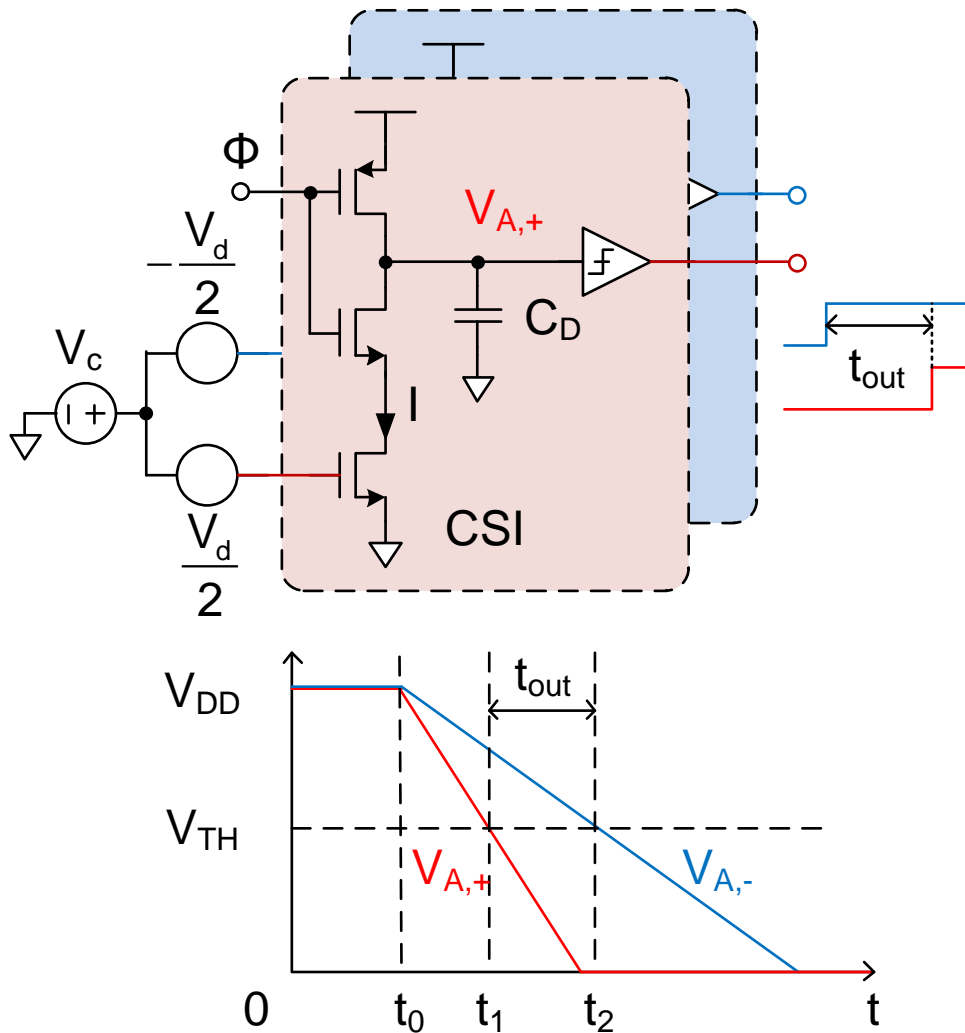
w/ PSR



w/o PSR



Linearity of VTC



- CSI-based VTC

$$t_1 - t_0 = (V_{DD} - V_{TH}) \cdot \frac{C_D}{I} = \frac{K}{V_{ov}^2}$$

- Differential output time

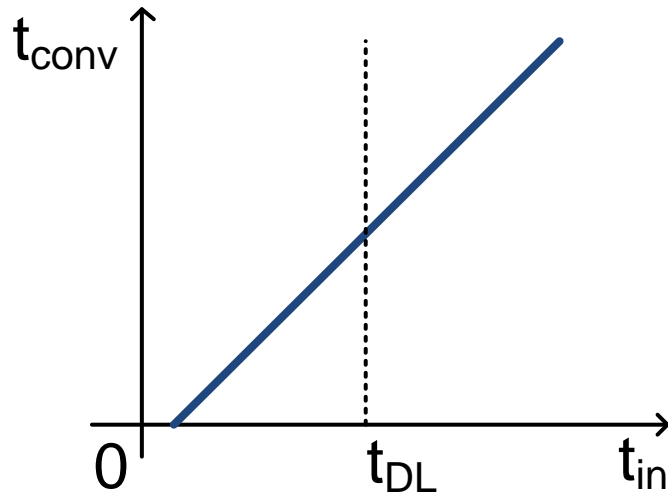
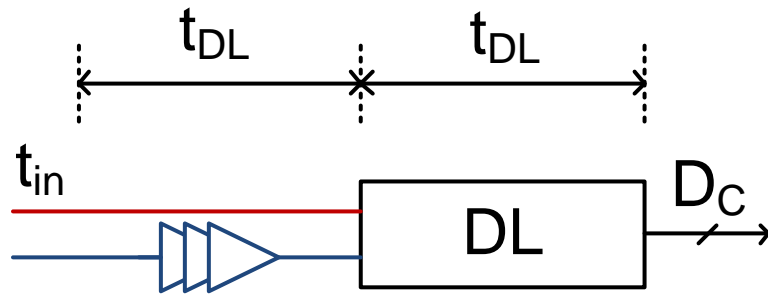
$$t_{out} = K \cdot \left(\frac{1}{V_{ov,+}^2} - \frac{1}{V_{ov,-}^2} \right)$$

$$= - \frac{2K(V_c - V_{tn})V_d}{(V_c - V_{tn} + V_d/2)^2 \cdot (V_c - V_{tn} - V_d/2)^2}$$

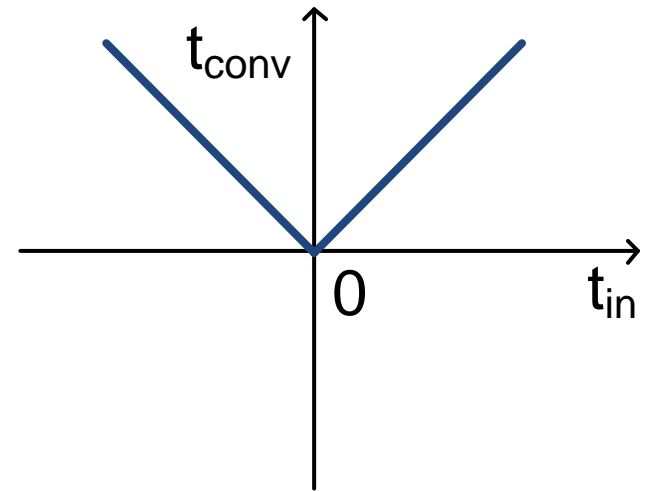
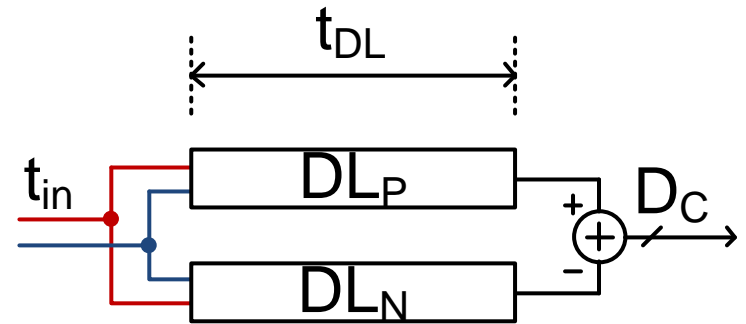
$$\text{If } (V_c - V_{tn}) \gg \left| \frac{V_d}{2} \right|, t_{out} \approx \frac{2K}{(V_c - V_{tn})^3} V_d$$

- $V_c \uparrow$, linearity \uparrow

Coarse TDC



[5] Macpherson, CICC13

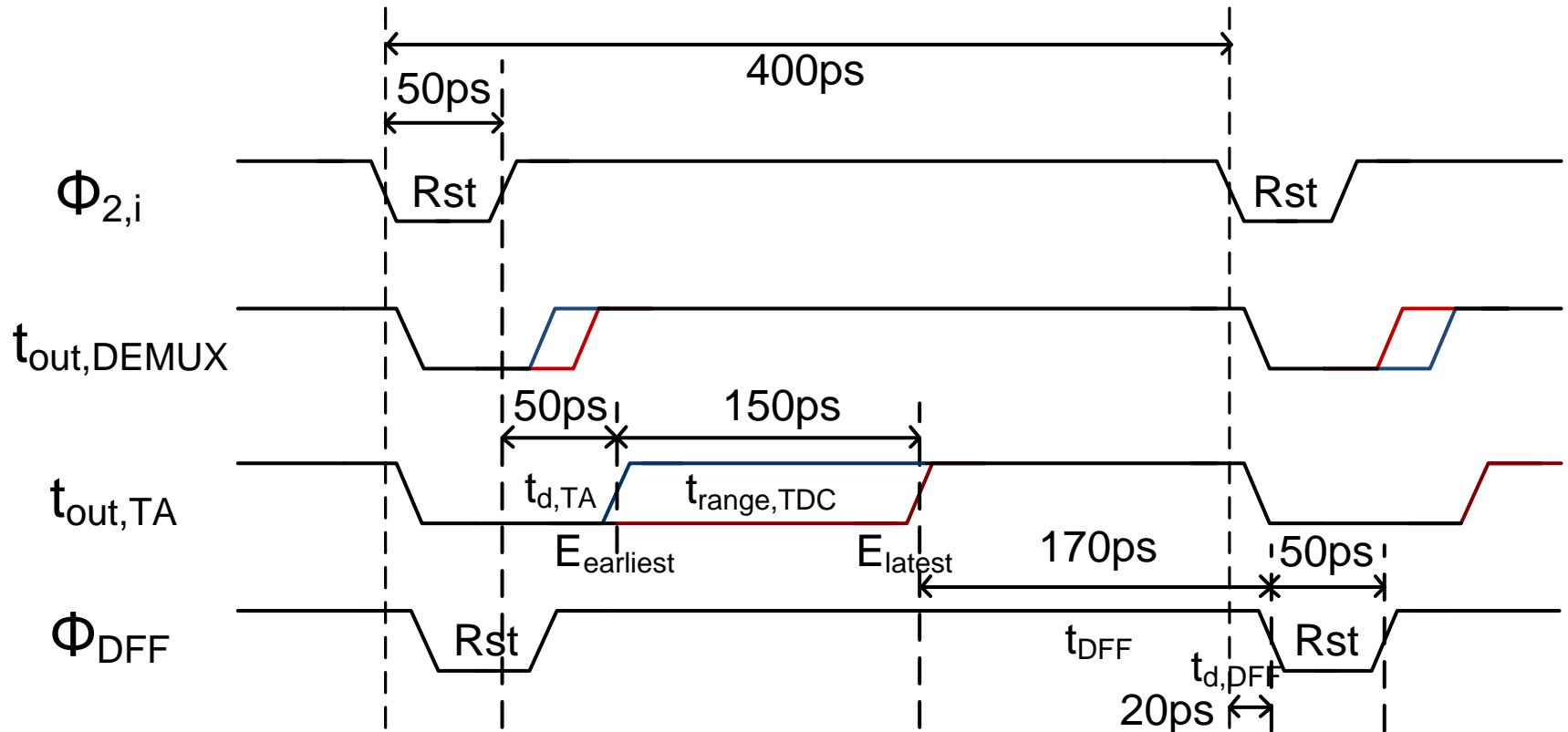


[4] Stephan, 2010

- Offset DL
- Twice conv. time cost

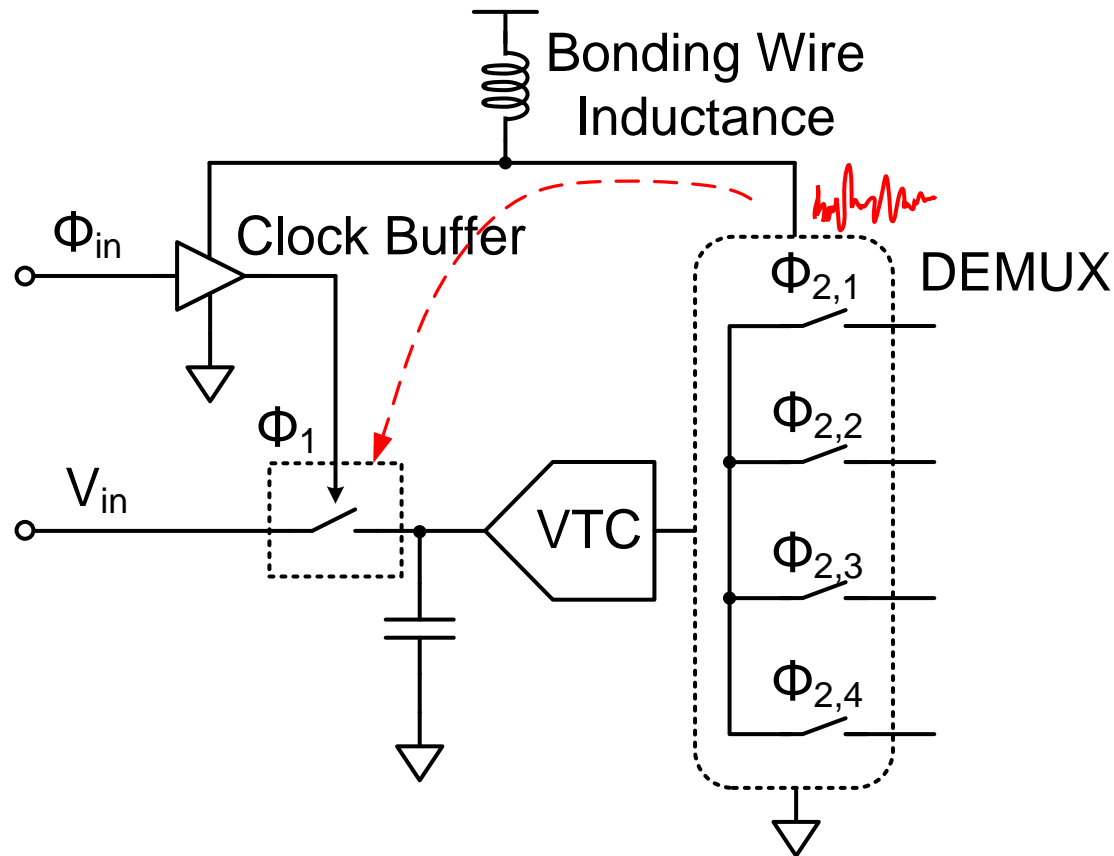
- Folded Differential DL
- No extra conv. time cost

Timing Diagram of TDC



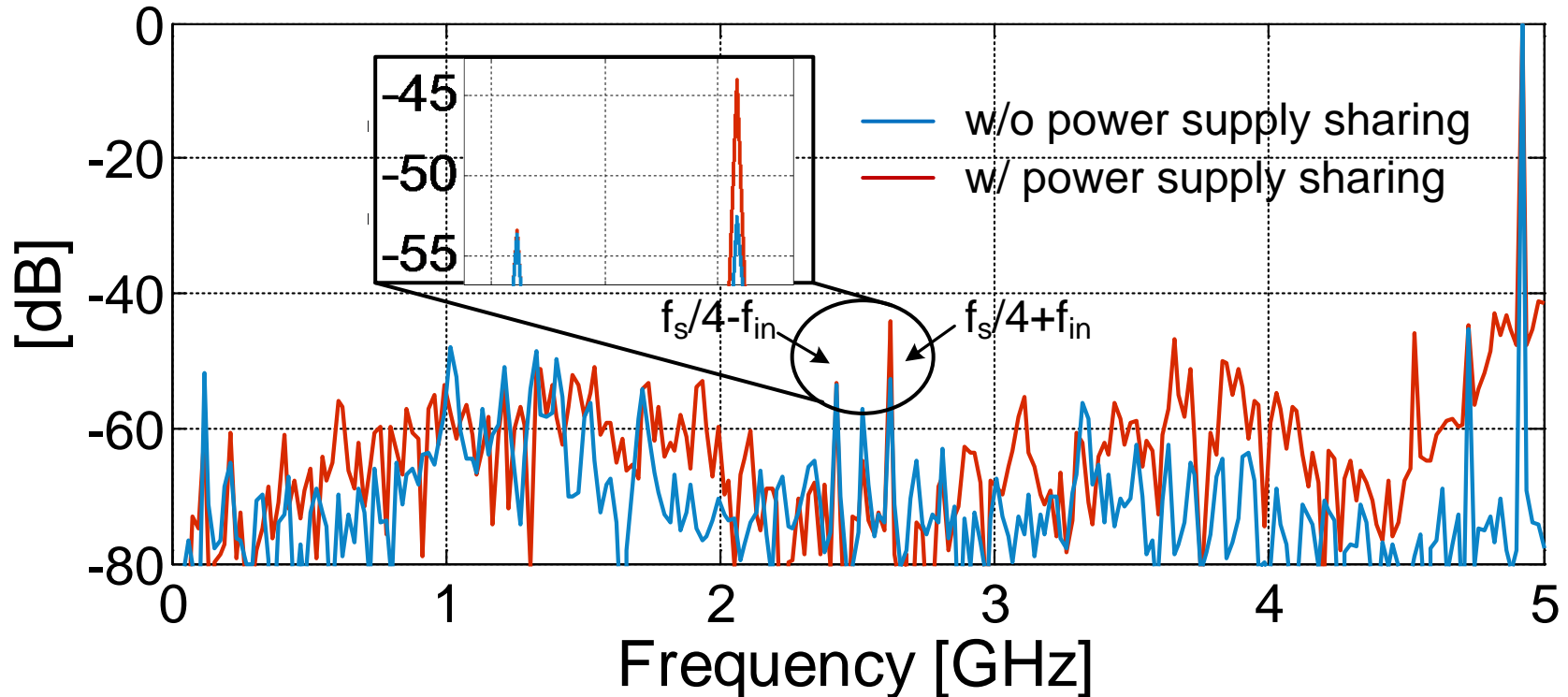
- Each channel has 400ps to complete quantization

Residual Interleaving Tones



- Residual Interleaving tone – sharing of the power supply of the DEMUX and the T/H's clock driver

Residual Interleaving Tones



- Post-layout simulation shows obvious residual interleaving tones with shared power supply